



SEY and Clearing Studies at KEKB



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- Introduction
- Studies
 - Beam duct with Ante-chambers
 - Coatings with Low SEY
 - Clearing Electrodes (plan)
- Summary



Introduction



○ Studies on ECI at KEK B-factory (KEKB)

- Using positron ring (LER)
 - $E = 3.5 \text{ GeV}$, $I = \text{max.} 1.7 \text{ A}$, 1.2 mA/bunch ($1.2 \times 10^{-8} \text{ C}$)
 - Usually ~ 1400 bunches, $6 \sim 8 \text{ ns}$ bunch spaces
 - Beam duct : $\phi 94 \text{ mm}$
- Experiments to suppress electron emission
 - Solenoid field
 - *In situ* SEY measurement
 - Beam duct with ante-chamber
 - Coatings with low SEY
 - Clearing Electrode [Plan]

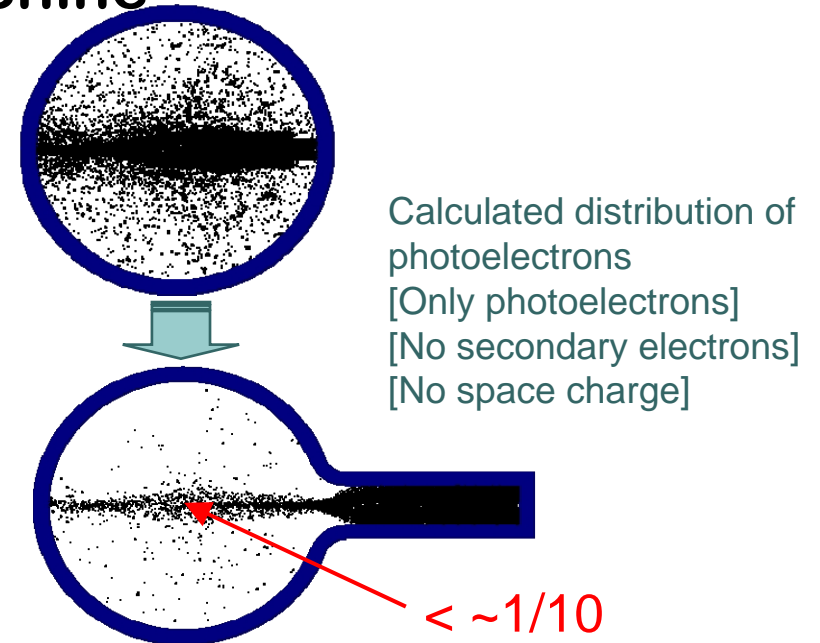
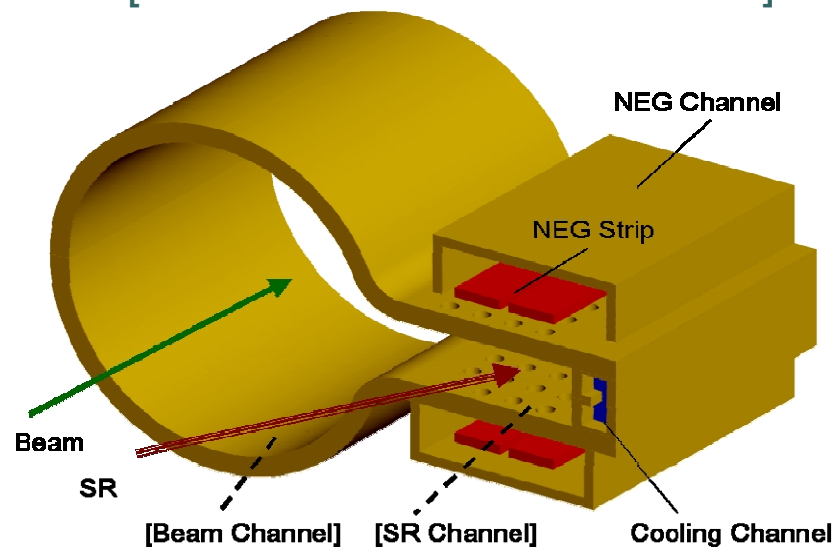
→ Here the results and plans are briefly reviewed.



Beam Duct with Ante-chambers

- Beam duct with ante-chamber (2003~):
 - Effective to reduce photoelectrons in beam channel
 - Also effective to dilute power density of SR
 - Important for high intensity machines: ex. Super B-factories
- Use copper for high current machine

[Beam duct with antechamber]



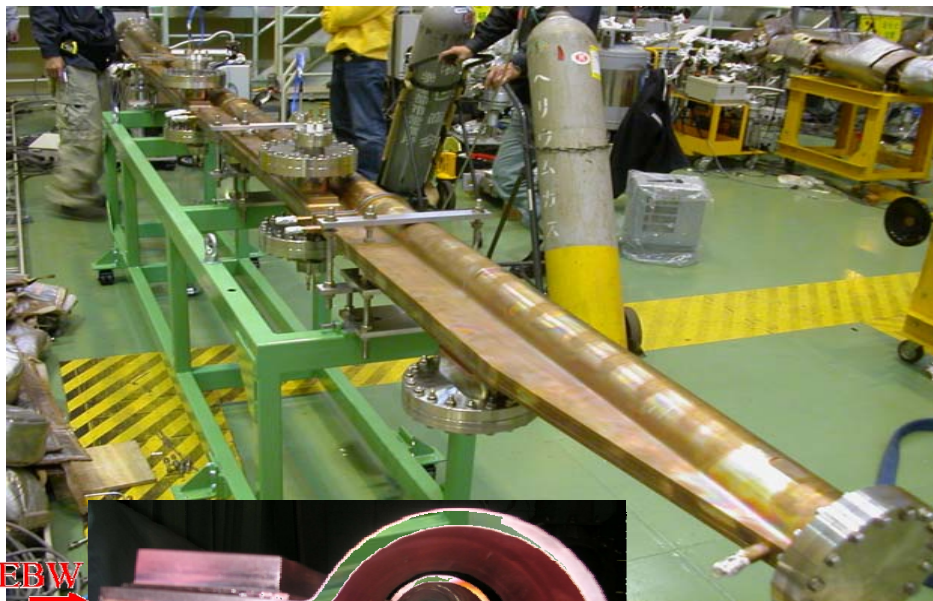


Beam Duct with Ante-chambers

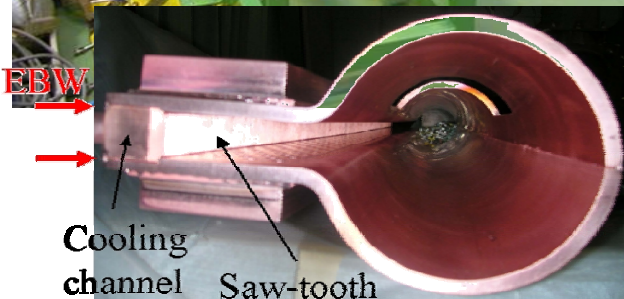
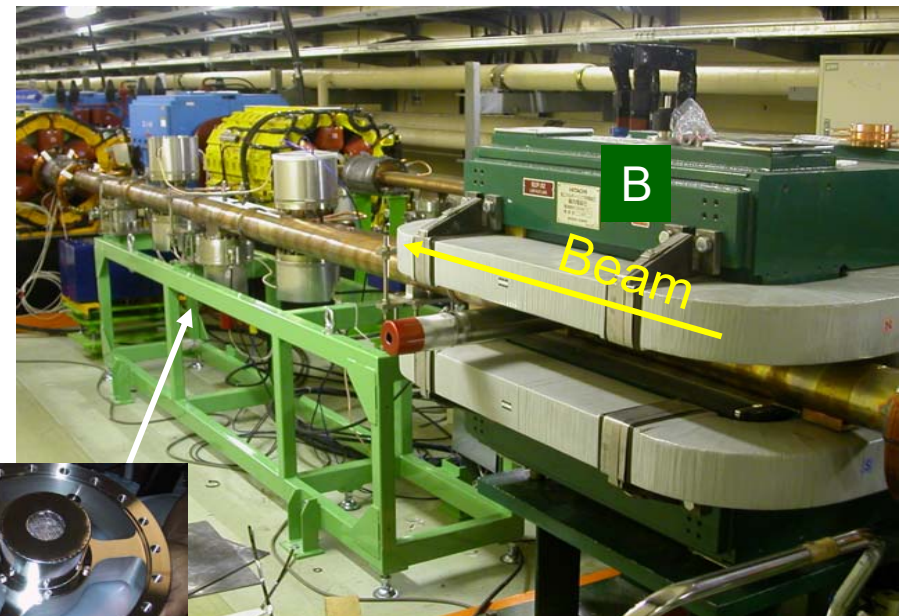


- Copper ducts with an antechamber was manufactured
 - Installed in the KEKB positron ring
 - **Electron current was measured using an electron monitor**

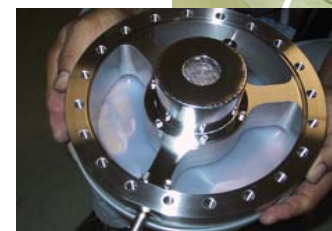
[Test duct (pressing)]



[Installed test duct]



EBW
EBW
 $\phi = 94 \text{ mm}$
 $h_a = 112 \text{ mm}$
 $t = 6 \text{ mm}$



Electron Monitor
(DC, Collector:+100 V, Repeller:-30V)

2007/03/1-2

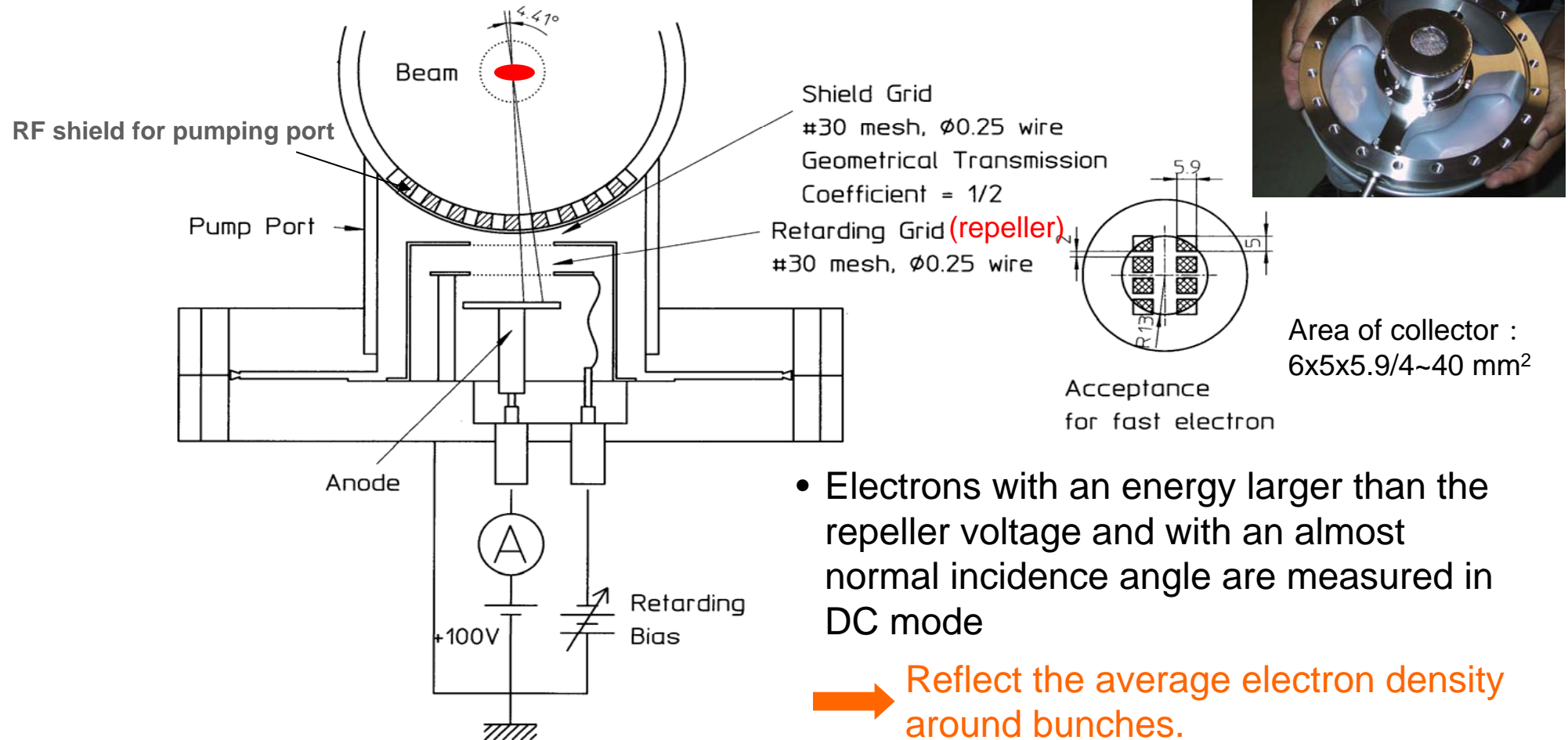
ECL2, CERN



Beam Duct with Ante-chambers

○ Electron Monitor

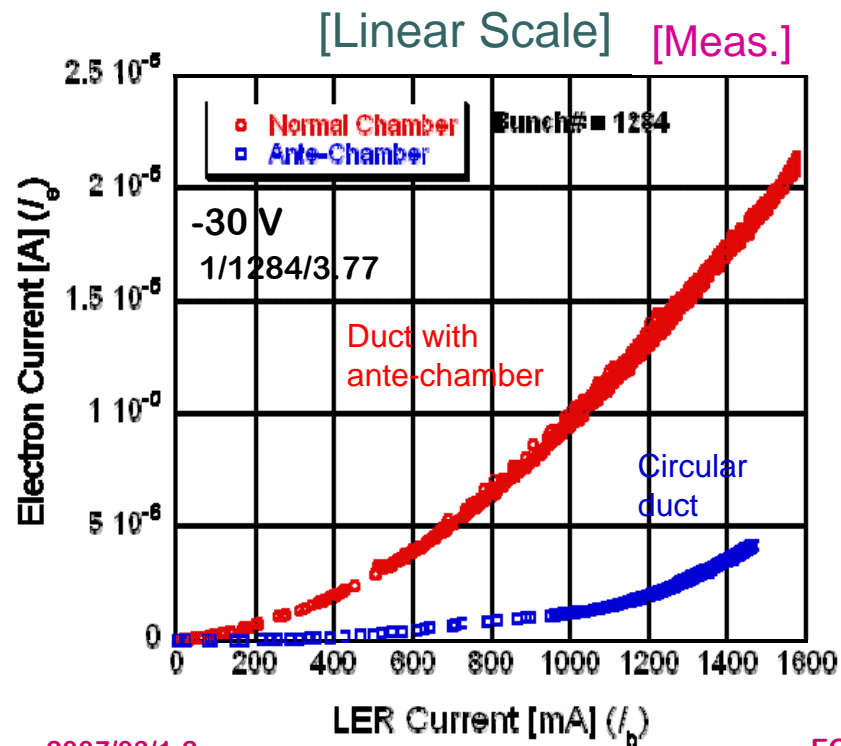
- Attached at the bottom of test chamber





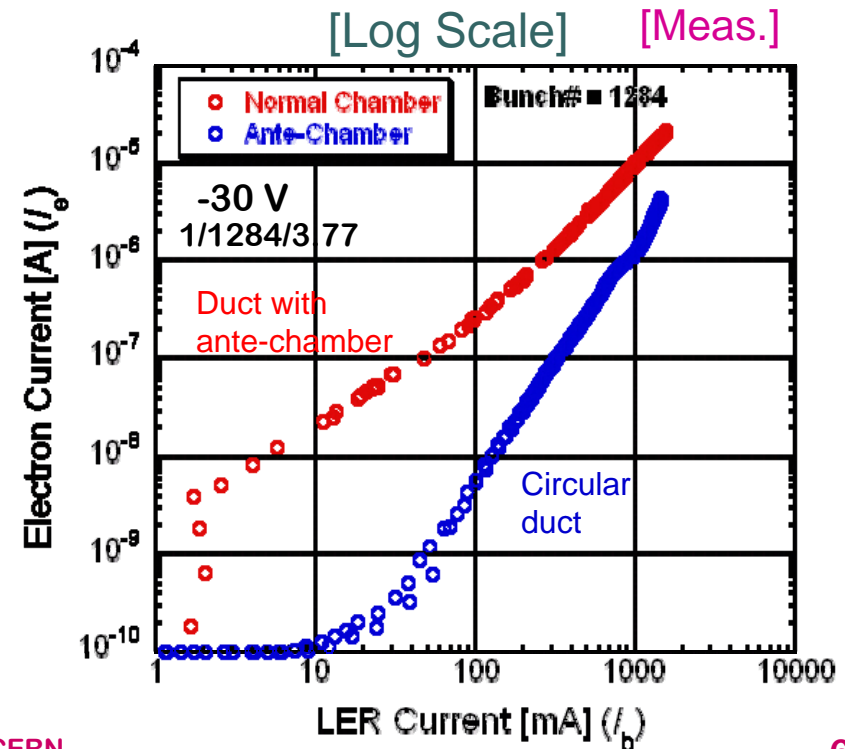
Beam Duct with Ante-chambers

- Comparison with simple circular duct.
 - At low current (<100 mA) : Reduction <1/100
 - Photoelectron is well suppressed.
 - At high current (>1500 mA): Reduction by a factor of 4
 - Secondary electron is important. → Surfaces with low SEY



2007/03/1-2

ECL2, CERN



6



Low SEY Coatings



- An essential way to suppress ECI at high current region
- Promising candidates:
 - **TiN coating**
 - Has long history for various apparatus.
 - **NEG coating**
 - Developed by CERN and SAES Getters.
 - Has pumping effect.
 - **Rough surface (groove)**
 - Proposed from BINP and SLAC
 - R&D is undergoing
 - **DLC (Graphite), or Graphitization**
 - Need further R&D

Focused on
at KEKB



Low SEY Coatings



○ Methodology

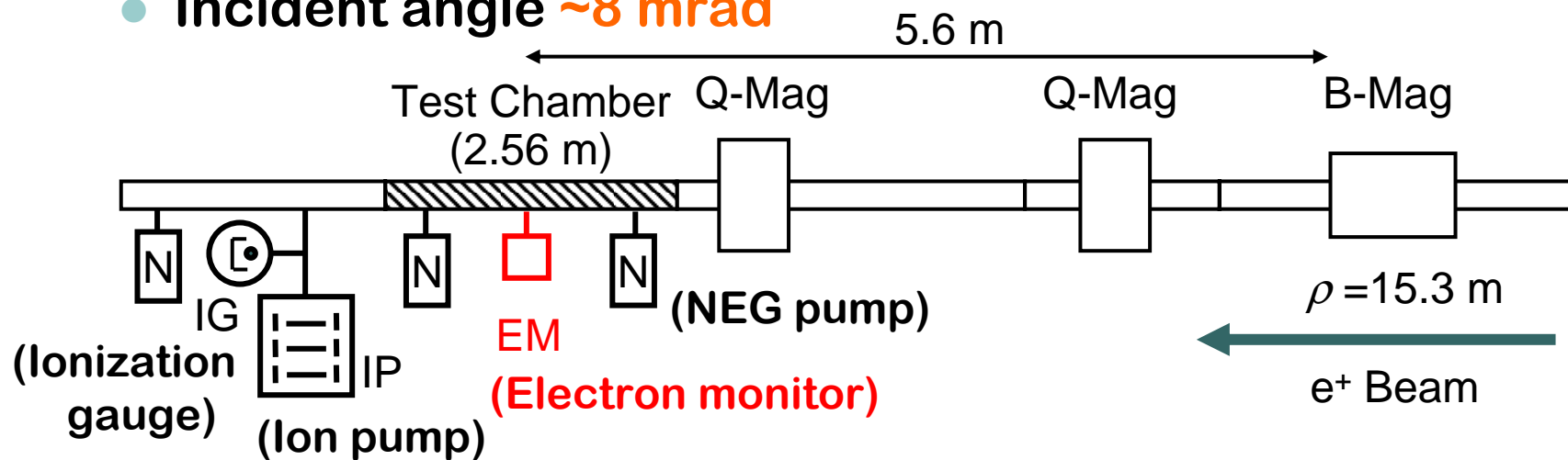
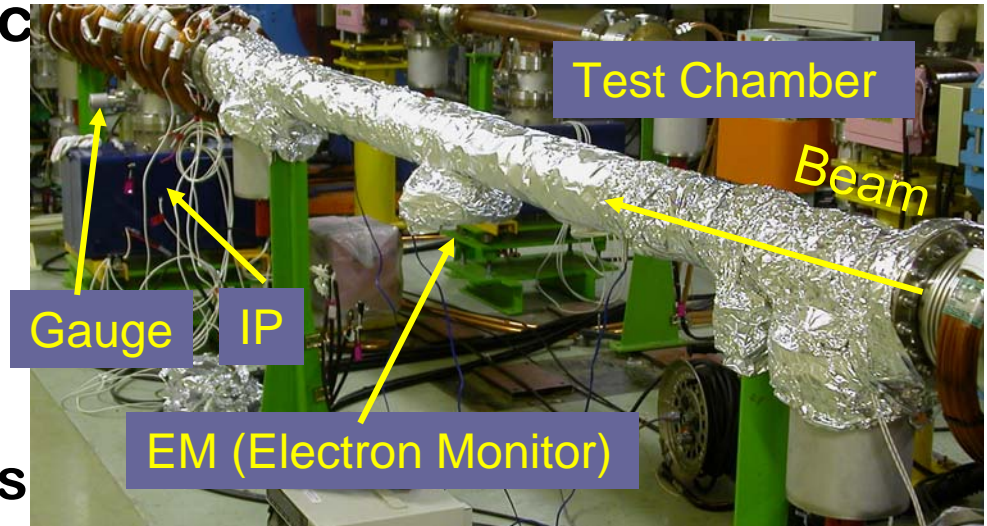
- **Test chambers** (Cu, TiN-coated and NEG-coated) were installed in the KEKB positron ring.
- Number of electrons near the beam orbit was measured using **an electron monitor**, and compared each other.
- **Photoelectron yield and secondary electron yield was estimated** using a simulation of electron current.



Low SEY Coatings

Ex.1: Measurement at an arc section (2004~)

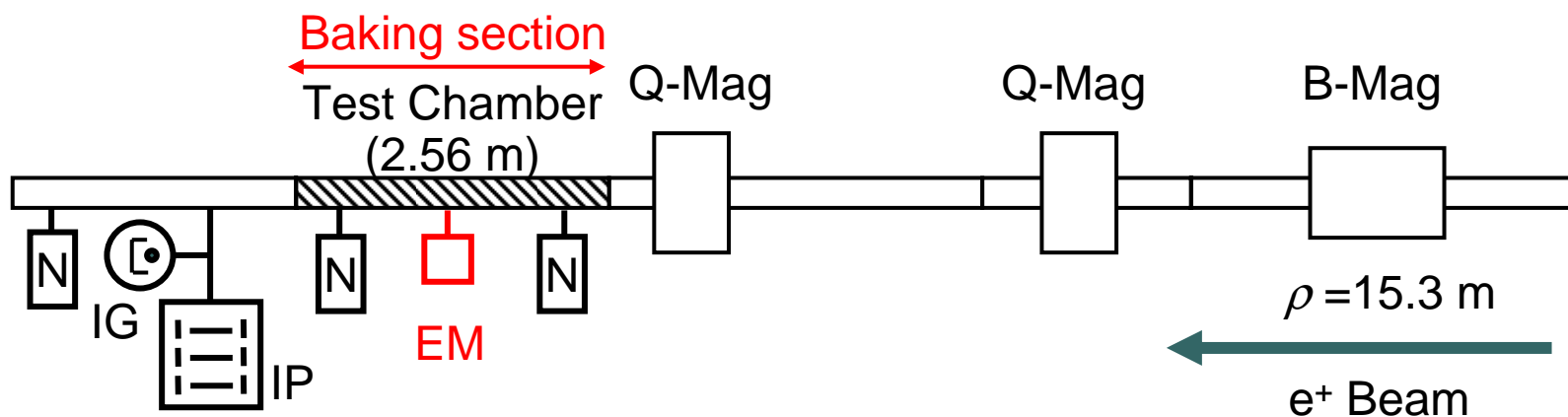
- Direct SR of 6.4×10^{14} photons/s/m/mA was irradiated at side wall.
- Realistic condition including photoelectrons
- Incident angle ~ 8 mrad





Low SEY Coatings

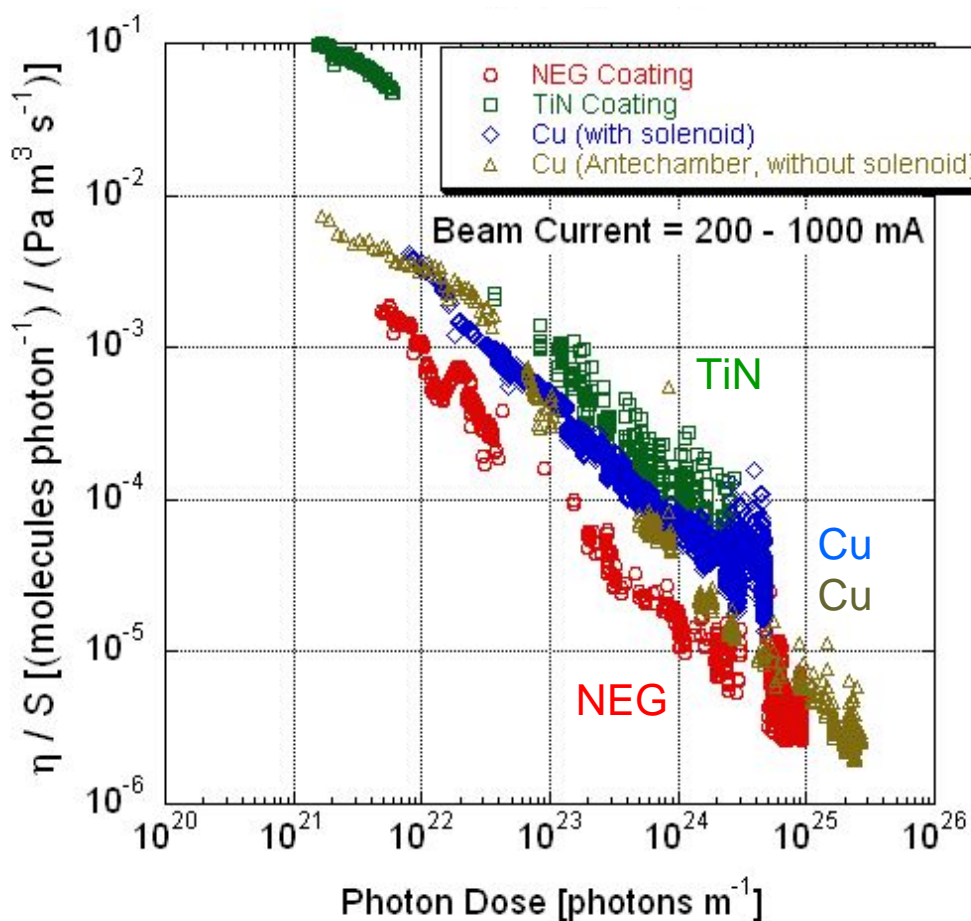
- Test chambers were baked before the installation at 150°C for 24 hours.
- **NEG-coated chamber** was **baked *in situ*** after the installation for at 180°C 6 hours followed by at **200°C for 2 hours**.
 - Only test chamber
 - No *in situ* baking for TiN-coated chamber





Low SEY Coatings

○ Vacuum scrubbing

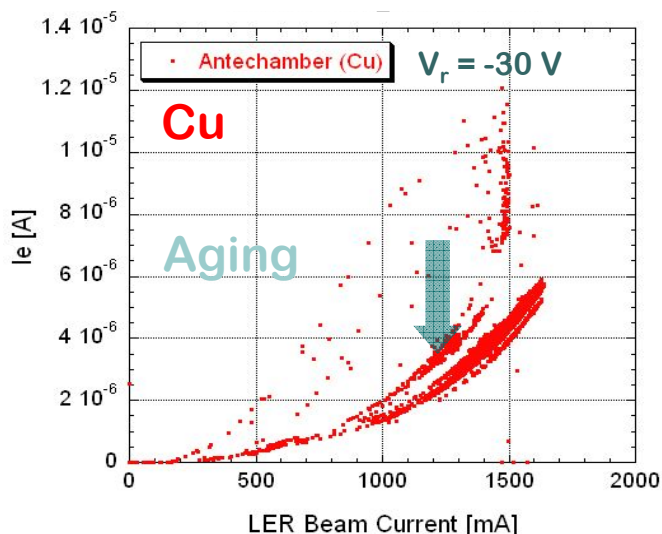


- **NEG-coated chamber is the lowest.**
 - By a factor of 5 @1E24 ph./m compared to copper.
 - Low gas desorption rate, and pumping in itself.
 - But not so prominent as reported so far.
 - ← Only one chamber was baked.
- TiN-coated chamber was much higher than copper at first, but by a factor of 2 at 1E24 ph./m.

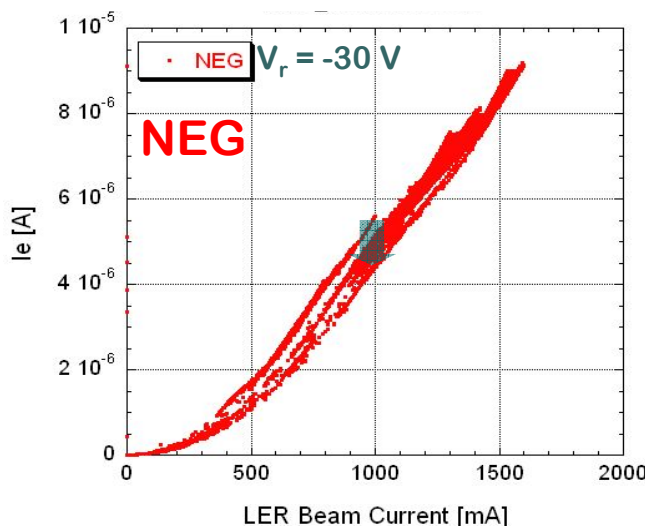


Low SEY Coatings

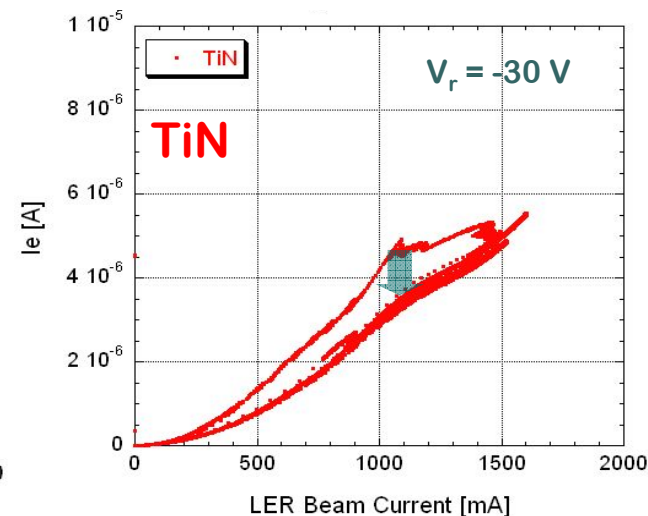
- Electron currents (I_e) were measured against beam current (I_b) in a usual beam operation.
- **Aging of SEY by electron bombardment** was seen at the beginning.



Antechamber (Cu)
A baking at 150°C 24 hours before installation



NEG
A baking at 200°C for 2 hours before operation in the tunnel to activate NEG



TiN
A baking at 150°C 24 hours before installation

Electron Dose : $4 \times 10^{-6} \text{A} / 1500 \text{mA} / 40 \text{mm}^2 \sim 7 \times 10^{-11} \text{C/s/mA/mm}^2$

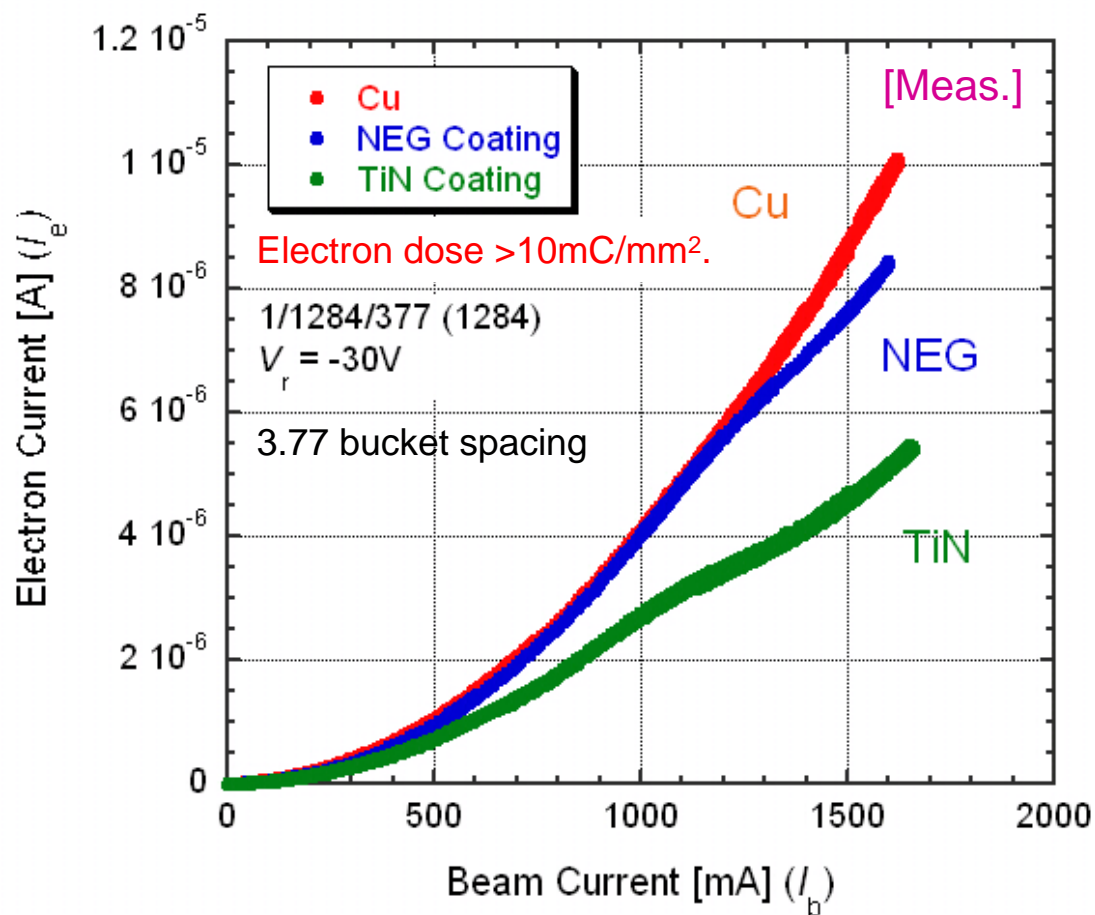
40 A hours: $7 \times 10^{-11} \times 40000 \times 3600 \sim 1 \times 10^{-2} \text{C/mm}^2 = 10 \text{mC/mm}^2$, ~2 days at



Low SEY Coatings

○ Cu, TiN, NEG for the same beam condition

(After sufficient aging)



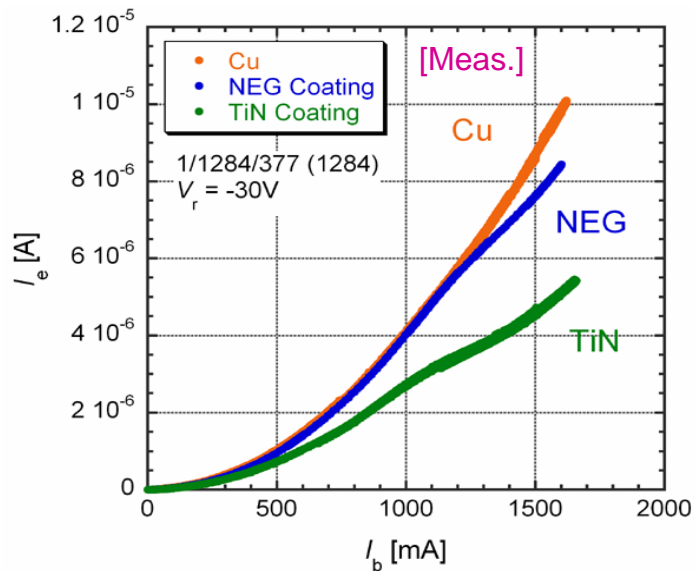
- I_e for NEG coating is almost same as that of Cu, except for high current.
- I_e for TiN coating is clearly lower than those for Cu and NEG (1/2 ~ 1/3).
- TiN seems better from the view point of small electron numbers in the beam duct.
- Little difference even after additional baking of NEG-coated chamber at 220°C for 2 hours.



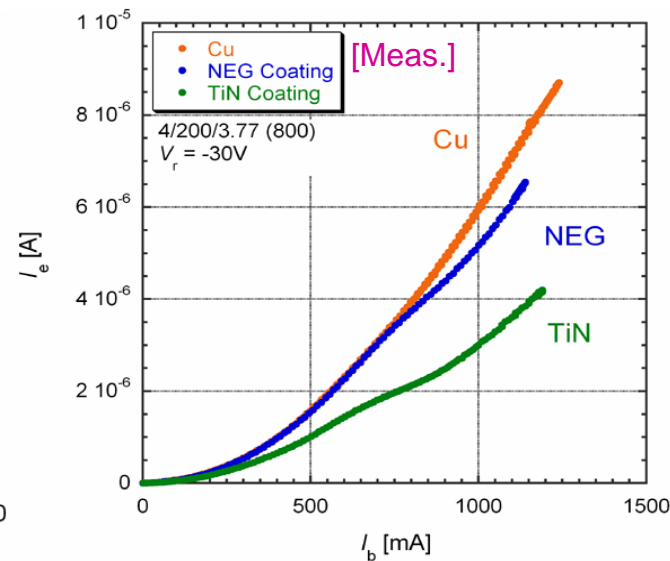
Low SEY Coatings

- Dependence on bunch filling pattern
 - For every case, $I_e(\text{Cu}) \sim I_e(\text{NEG}) > I_e(\text{TiN})$

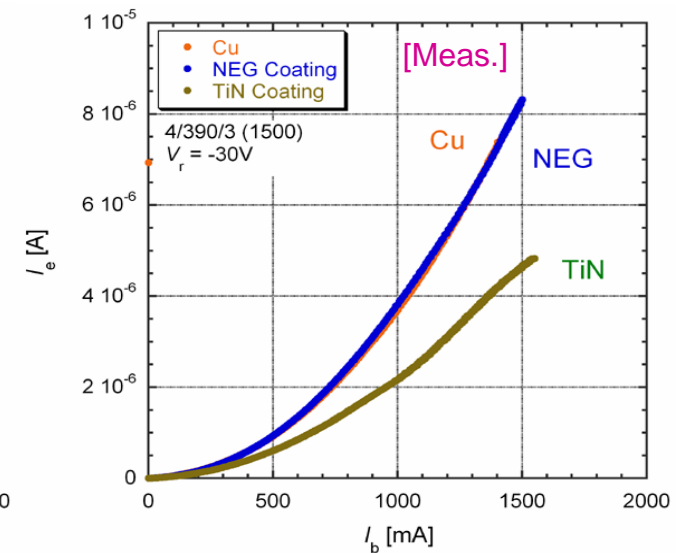
1/1284/3.77 (#1284)



4/200/3.77 (#800)



4/390/3 (#1500)



1 RF bucket = 2 ns

1 mA / bunch = 1×10^{-8} C / bunch = 6.2×10^{10} e⁻ / bunch



Low SEY Coatings

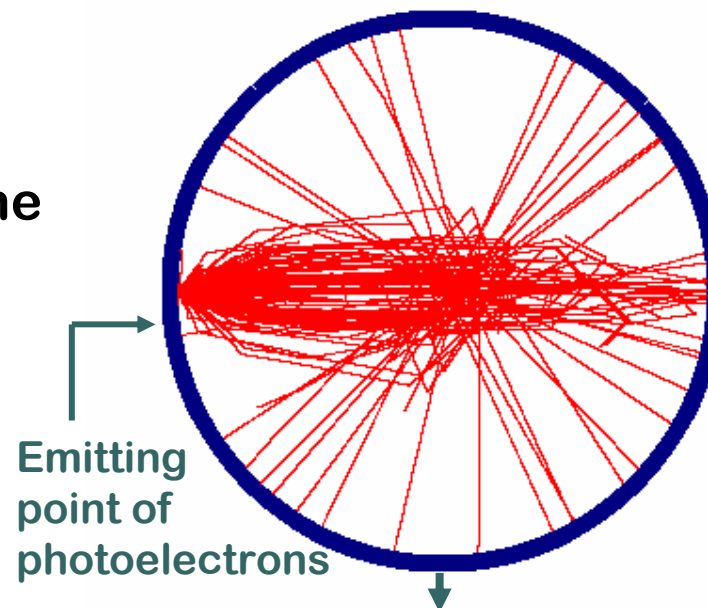
Simulation

- Understand the behavior of measured electron currents
- Estimate the SEY (δ_{\max}) and PEY (photoelectron yield, η_e) of Cu, NEG and TiN.

Method:

- “Macro” electrons ($\leq 10^4$ electrons) are traced from the emission, and the number of electrons hitting the bottom of duct (position of electron monitor) with an almost normal incidence angle are counted.
- η_e : Constant
- SEY: Follows Furman’s formula (constant profile with $E_{\max}=300\text{eV}$)

$$\delta(E) = 1.11 \times \delta_{\max} \times \left(\frac{E}{E_{\max}} \right)^{-0.35} \times \left[1 - \exp \left(-2.3 \times \left(\frac{E}{E_{\max}} \right)^{1.35} \right) \right]$$

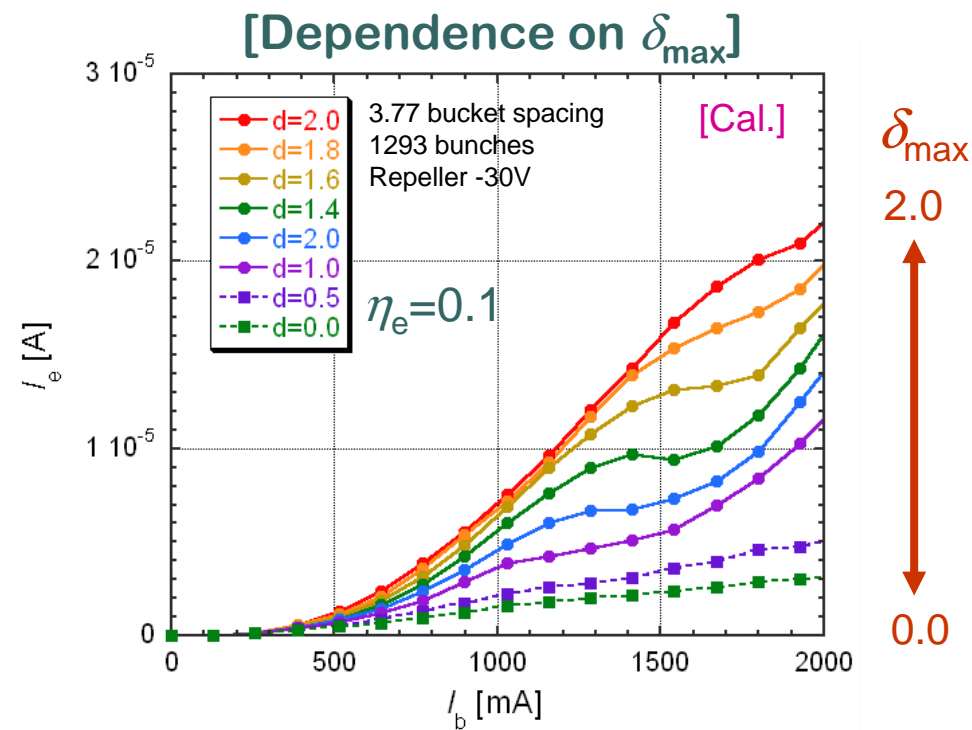
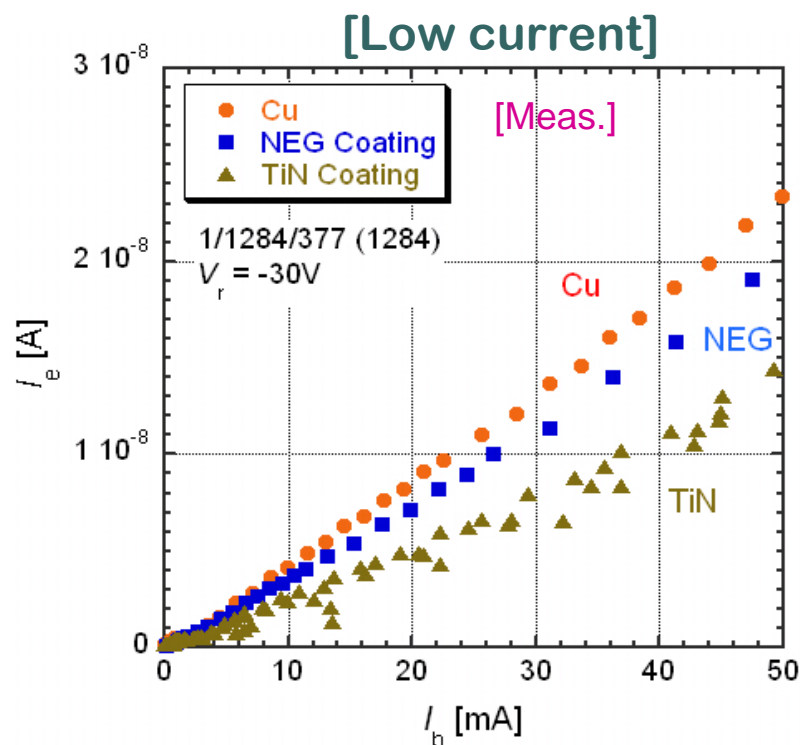


[Example of electron trajectories (Only photoelectrons, No secondary electrons, No space charge)]



Low SEY Coatings

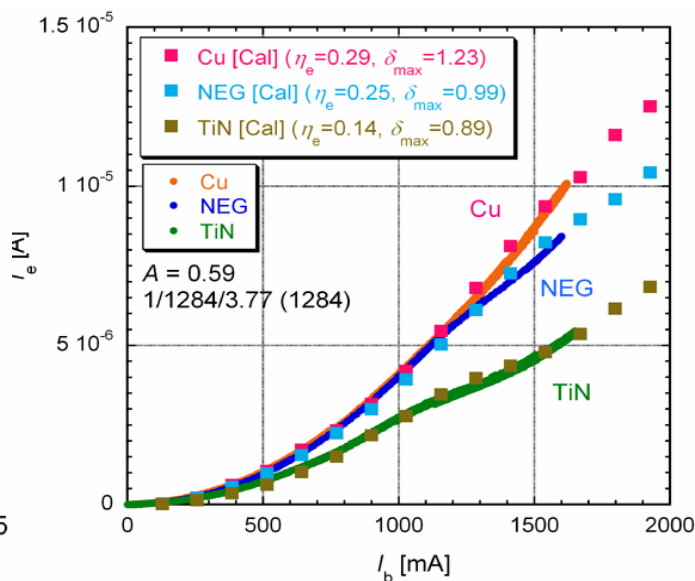
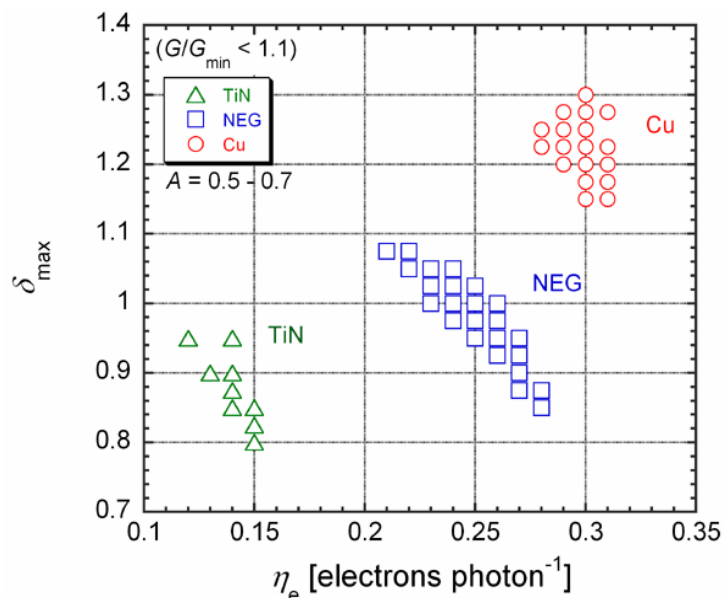
- I_e curves depend on η_e and δ_{\max} .
- Estimation of η_e and δ_{\max} by curve fitting:
 - I_e at low $I_b \rightarrow$ photoelectrons are dominant $\rightarrow \eta_e$
 - I_e at high $I_b \rightarrow$ secondary electrons are dominant $\rightarrow \delta_{\max}$





Low SEY Coatings

- Curve fitting by scanning photoelectron yield η_e ($0.1 \leq \eta_e \leq 0.4$) and Max. SEY δ_{\max} ($0.8 \leq \delta_{\max} \leq 2.0$).



3.77 bucket spacing
1293 bunches
Repeller -30V

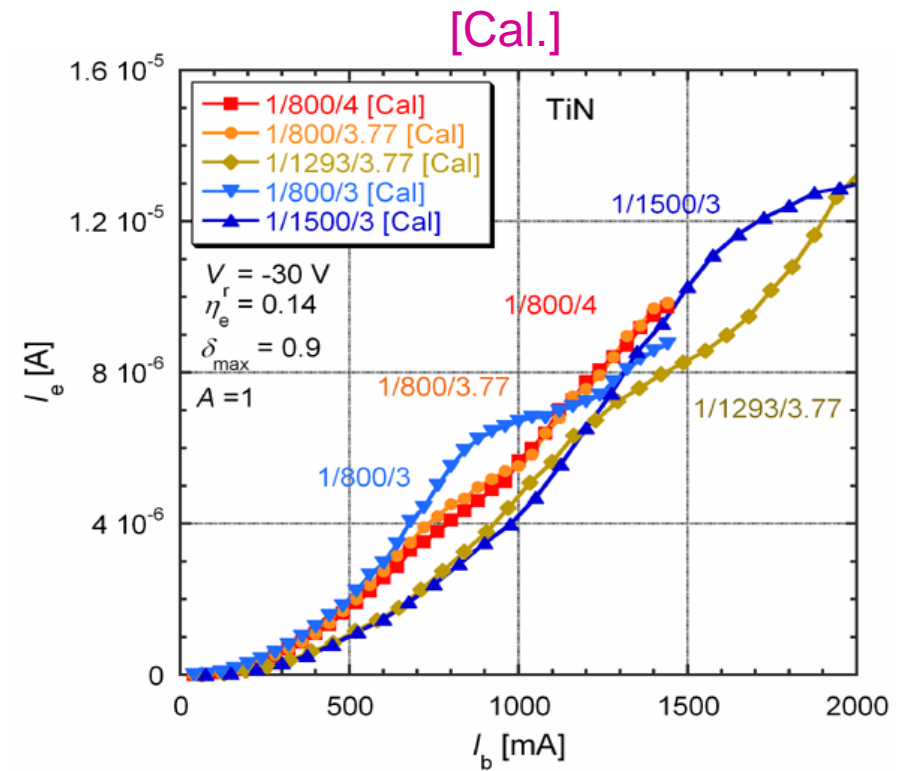
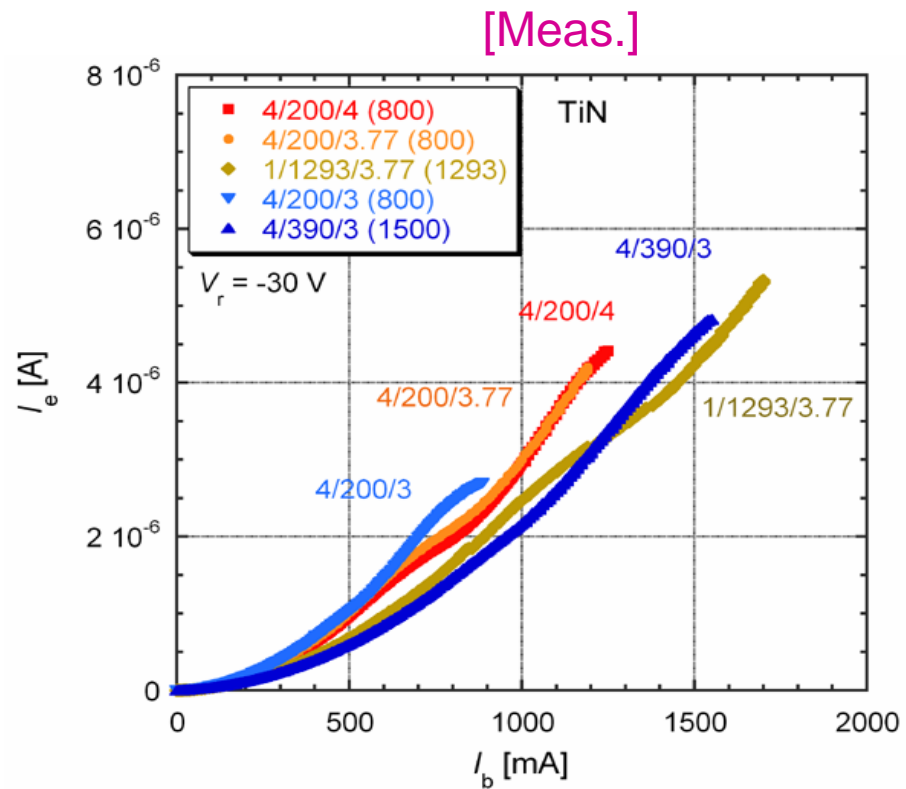
	η_e	δ_{\max}
Cu	0.28-0.31	1.1-1.3
NEG	0.22-0.27	0.9-1.1
TiN	0.13-0.15	0.8-1.0

- TiN coating seems better from view points of low δ_{\max} and also low η_e .
- δ_{\max} of NEG is lower than Cu, but not so clear due to the high η_e .
- The δ_{\max} of Cu, NEG and TiN is near to those measured in laboratory after sufficient electron bombardment.



Low SEY Coatings

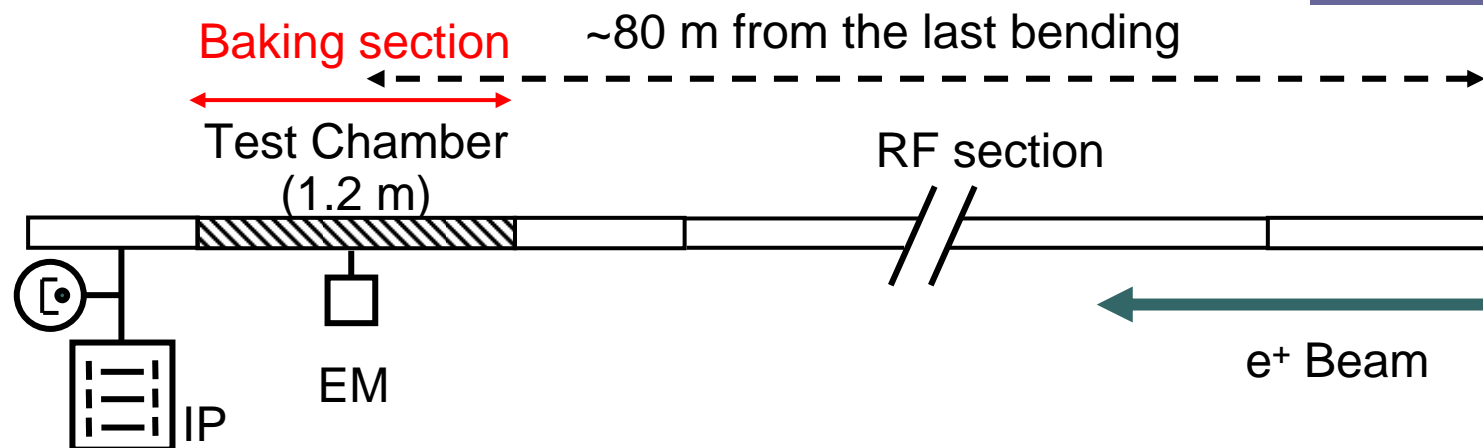
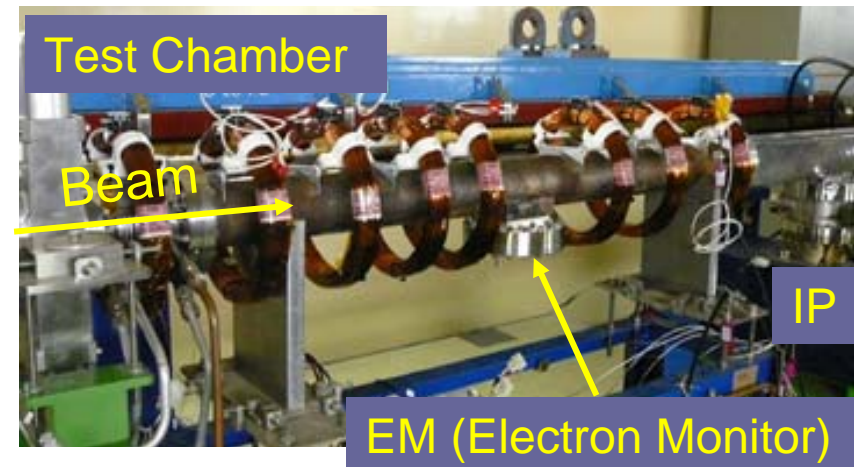
- Ref: Simulation well explained the dependence on bunch fill pattern.





Low SEY Coatings

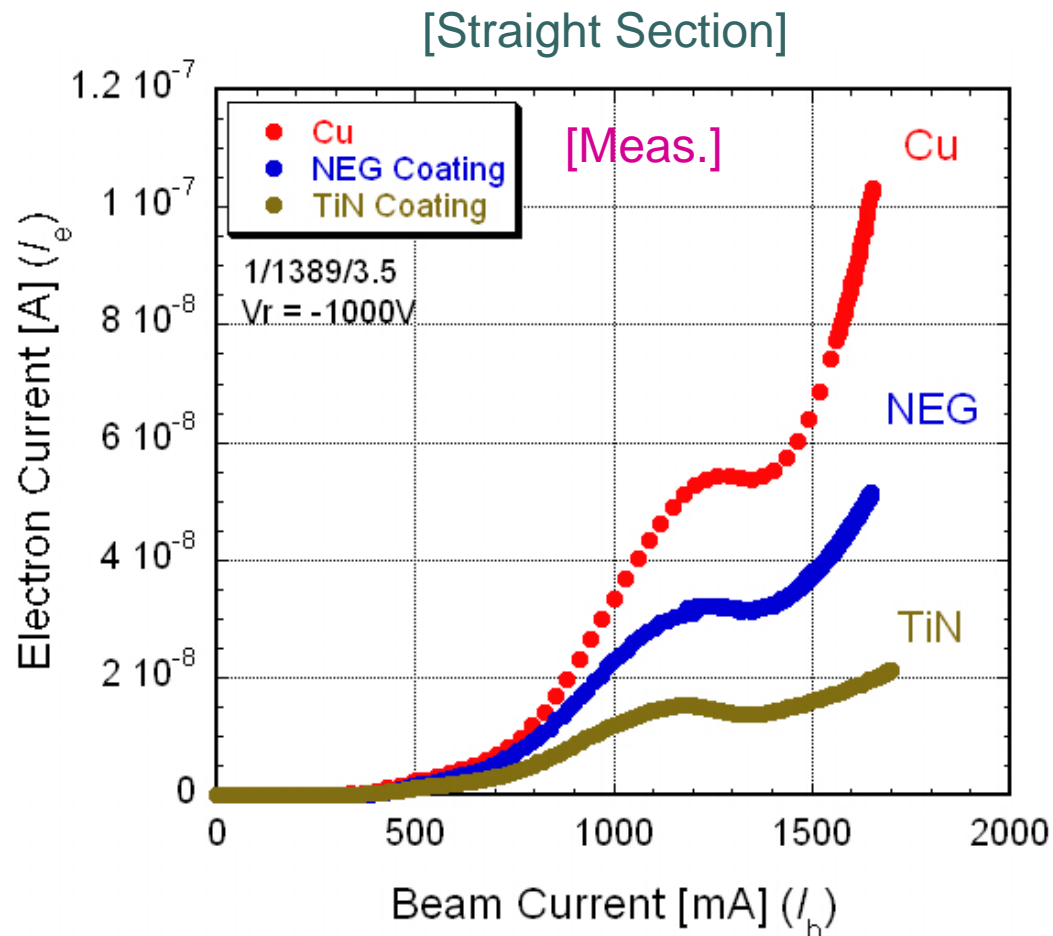
- Ex.2: Measurement at a straight section (2006~)
 - Low direct SR : 3.3×10^{12} photons/s/m/mA (<1/100 of arc)
 - Eliminate the effect of SR
- Copper, TiN coating and NEG coating
 - The same procedure to the experiment at arc section





Low SEY Coatings

- Measured electron currents (I_e) for Cu, NEG-coating and TiN-coating at the same condition

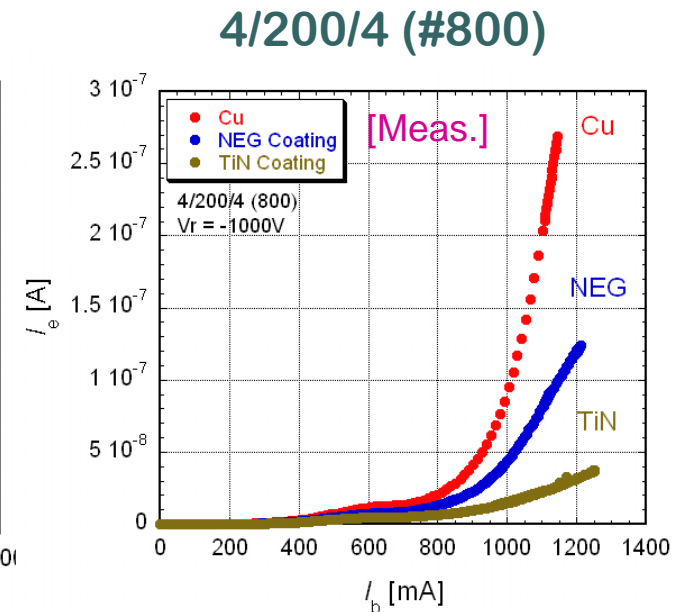
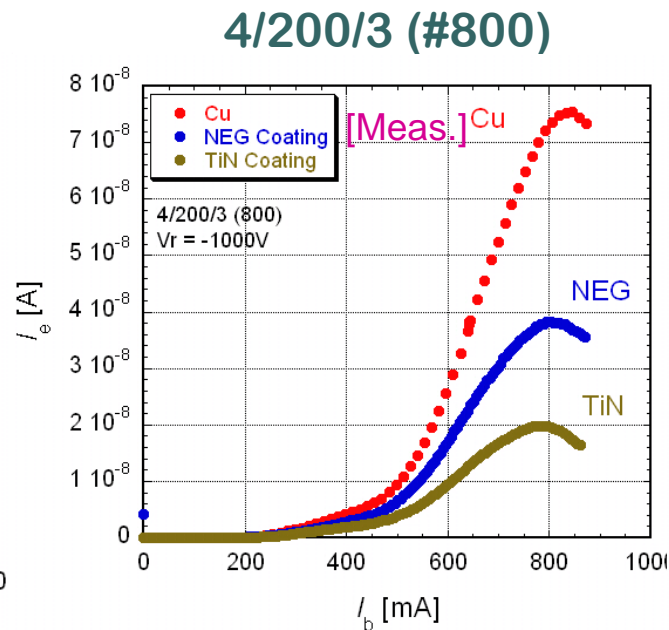
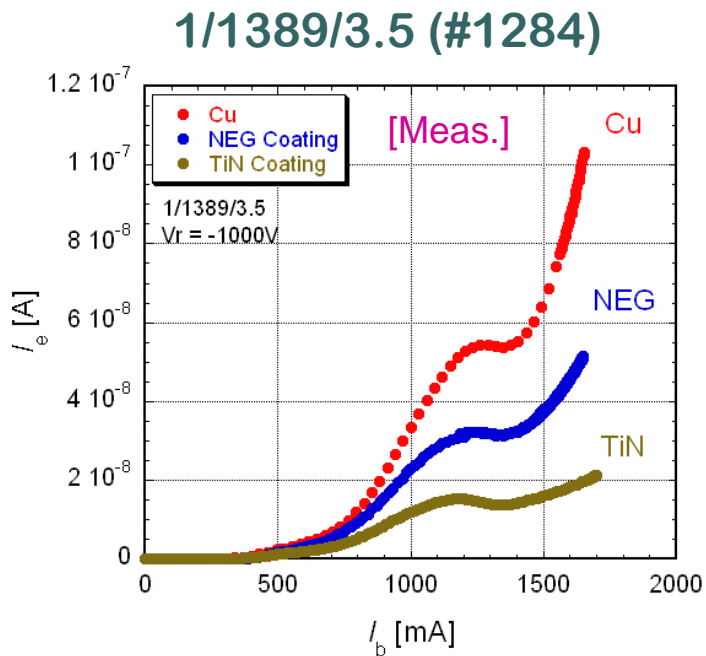


- I_e for NEG coating is 2/3 - 1/2 of that for Cu.
- I_e for TiN coating is 1/3 - 1/4 of that for Cu.
- NEG is clearly lower than Cu.
- TiN again seems better from the view point of small electron numbers in the beam duct.
- Little difference even after additional baking of NEG-coated chamber at 200°C for 2 hours.



Low SEY Coatings

- o Dependence on bunch filling patterns
 - For every case, $I_e(\text{Cu}) > I_e(\text{NEG}) > I_e(\text{TiN})$
 - Small direct SR made the effect of δ_{\max} clearer.



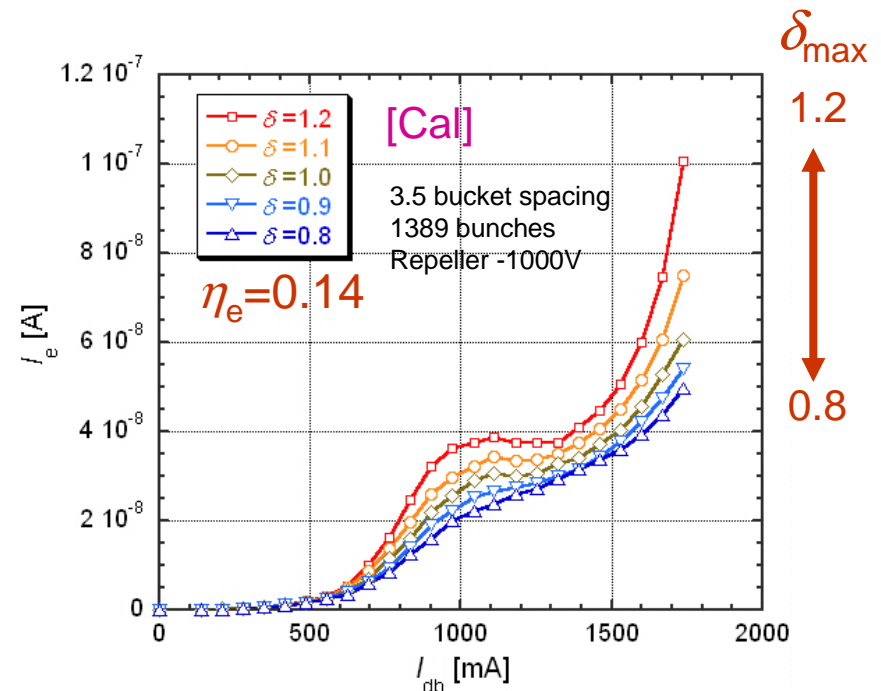
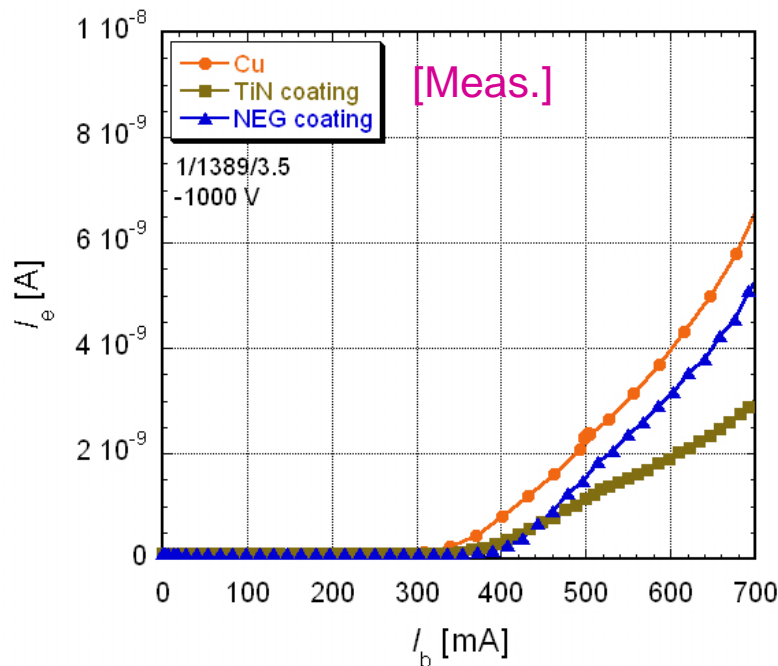
1 RF bucket = 2 ns

1 mA / bunch = 1×10^{-8} C / bunch = 6.2×10^{10} e⁻ / bunch



Low SEY Coatings

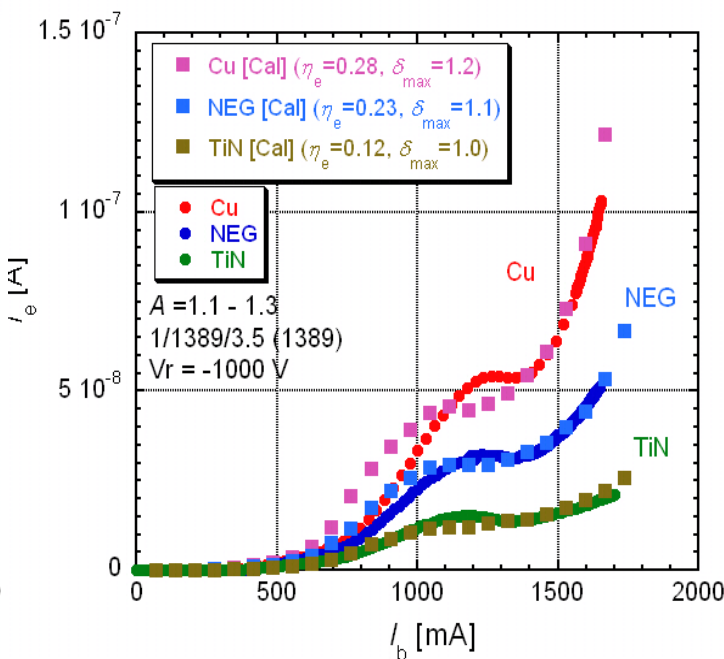
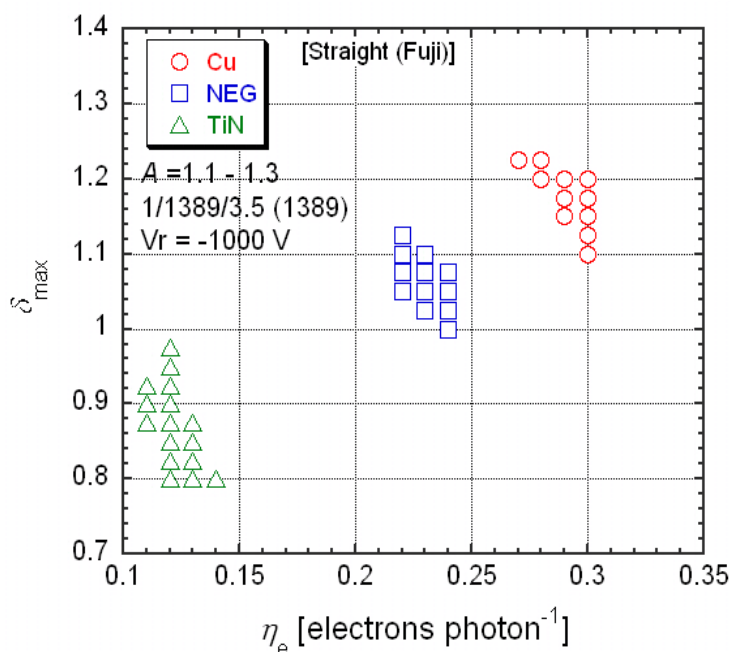
- I_e curves depend on η_e and δ_{\max} → curve fitting
- Estimation of η_e and δ_{\max} :
 - I_e at low I_b → too low current, and cannot measure I_e
 At $I_b = 400 \sim 600$ mA, $I_e(\text{Cu}) > I_e(\text{NEG}) > I_e(\text{TiN})$
 → assume the same η_e as before.
 - I_e at high I_b (>1500mA) → δ_{\max}





Low SEY Coatings

- Curve fitting by scanning photoelectron yield η_e and Max. SEY δ_{\max} .



3.5 bucket spacing
 1389 bunches
 Repeller -1000V

The same η_e were assumed.

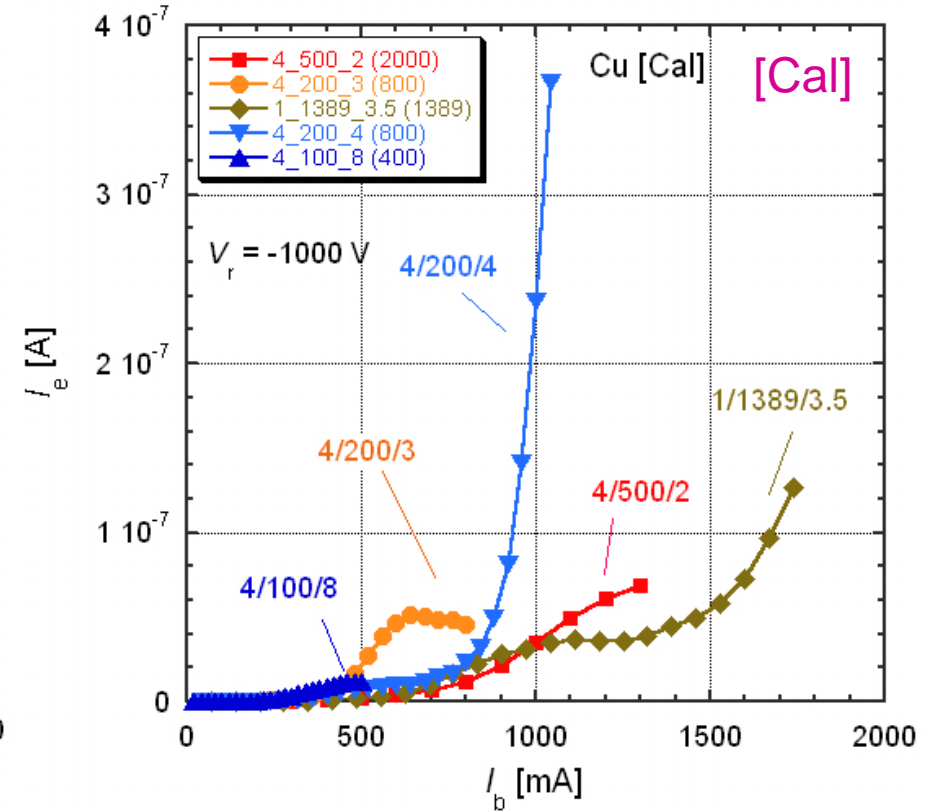
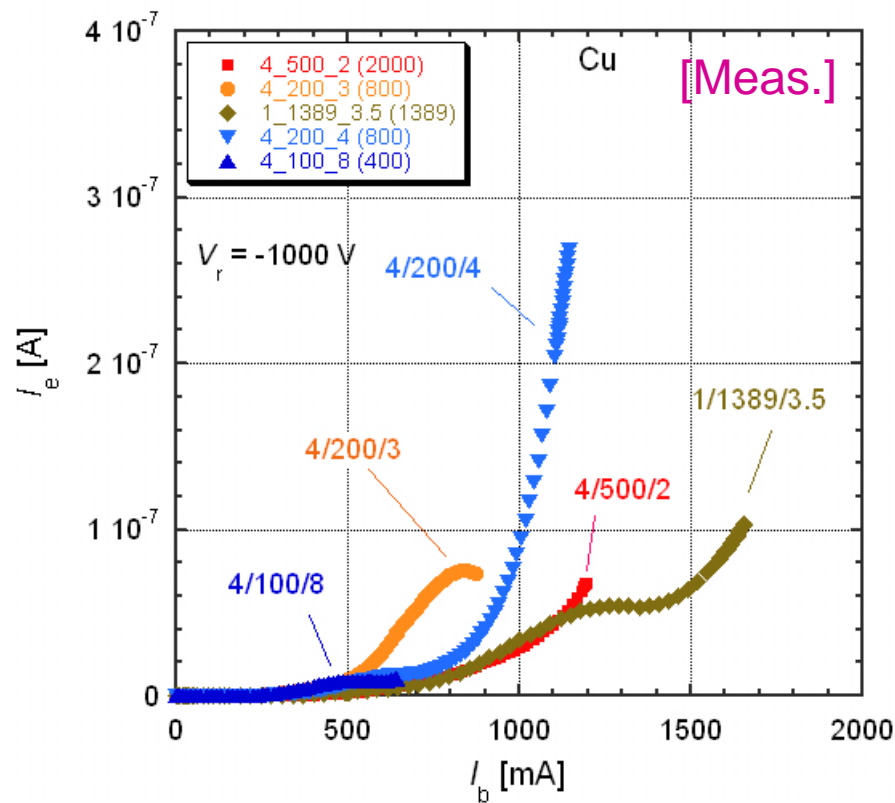
	η_e	δ_{\max}
Cu	0.28	1.1-1.25
NEG	0.23	1.0-1.15
TiN	0.12	0.8-1.0

- Measured I_e can be reproduced with estimated δ_{\max} and η_e , which are consistent with those obtained at arc section.
- TiN still seems better from a view point of low δ_{\max} and also low η_e .



Low SEY Coatings

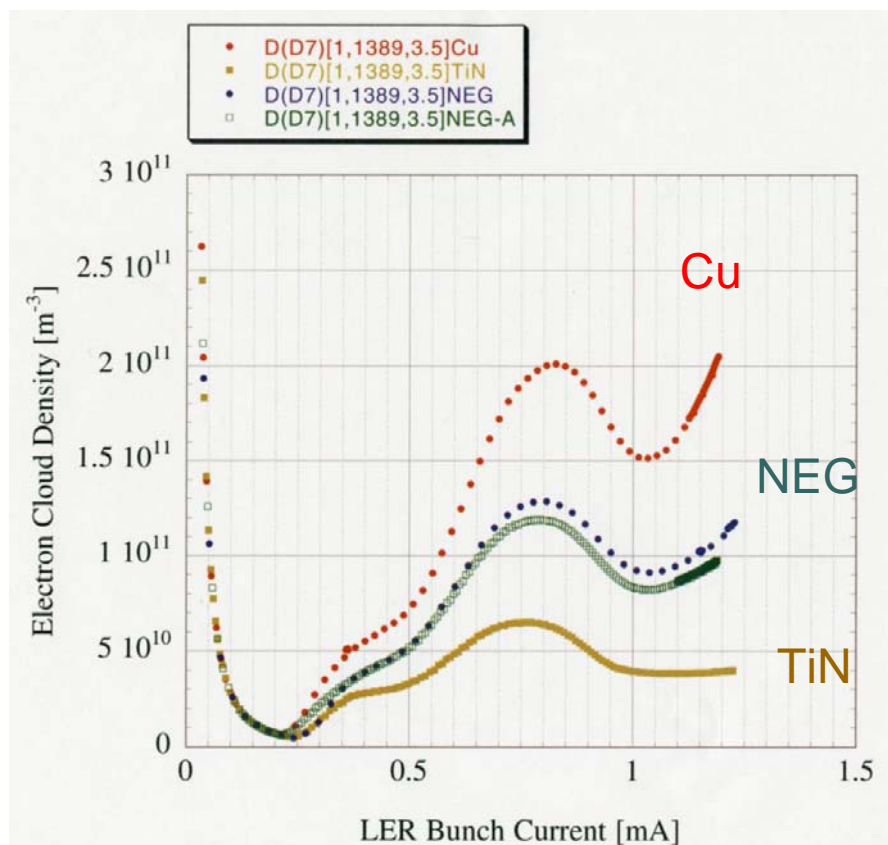
- Ref: The simulation well explained the dependence on bunch fill pattern.



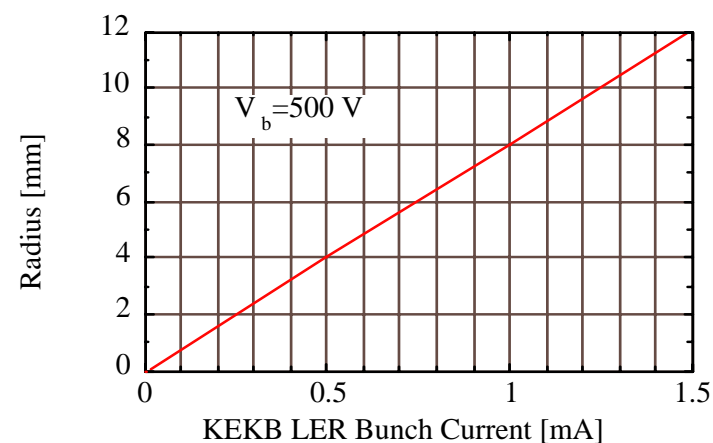


Low SEY Coatings

- Ref: Electron density can be estimated by the electron current at a high repeller voltage. (by K.Kanazawa, KEK)



- Repeller voltage = -1000V.
- Volume where electrons can obtain the energy was taking into account.
- Accuracy: in a factor of 3
[Region of acceleration]



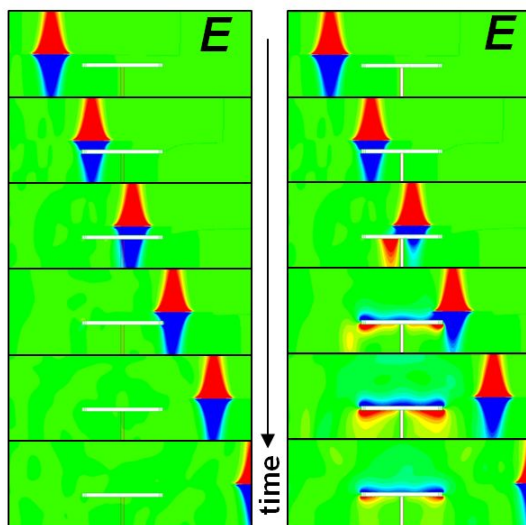
K.Kanazawa et al., PAC2005, p.1054



Clearing Electrode

- Effective in magnetic field
- Proposed here is a **rod type supported by a ceramics with thin metal coating (high resistivity)**
 - Little interference with beams
 - Idea was proposed by F. Caspers as “invisible electrode” (‘87)
 - Already adopted at DAΦNE as ion clearing electrodes
 - Similar structure had been pronounced as a collimator for KEKB

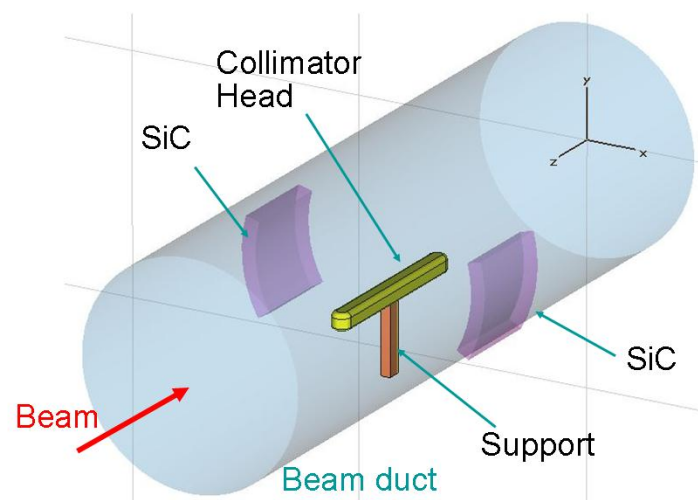
Interference with beam (MAFIA)



Ceramics ($\epsilon_r=4$)

Metal (Cu)

Concept of new collimator

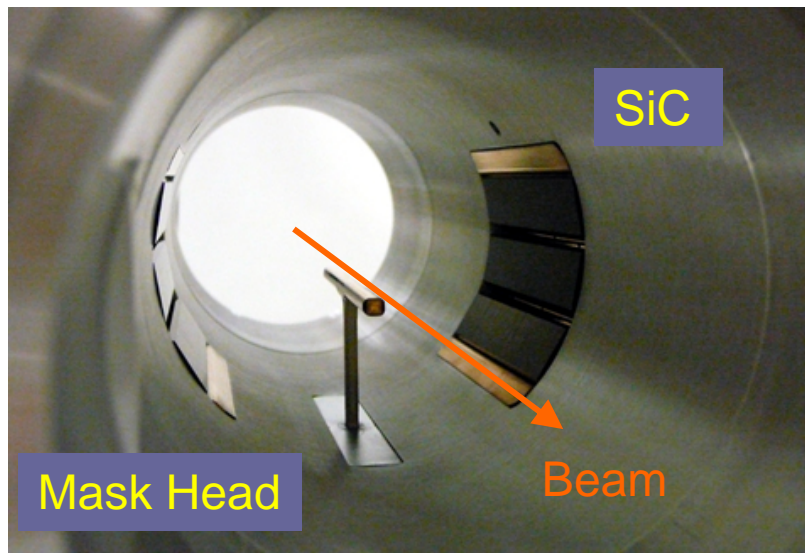




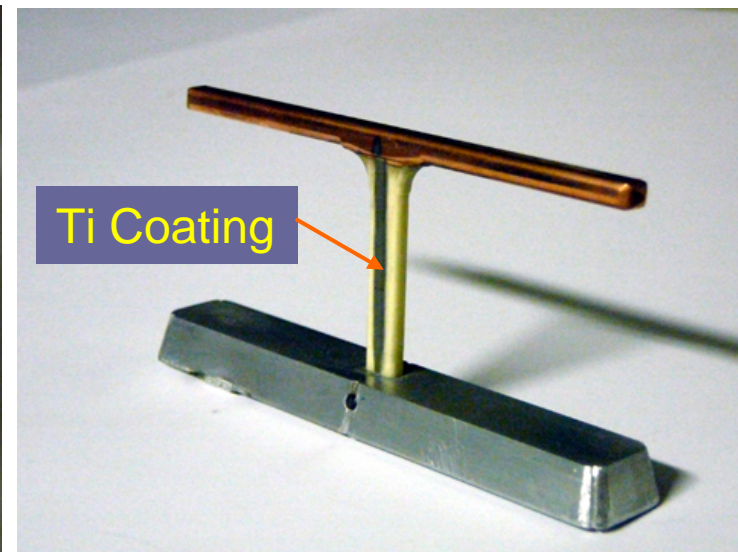
Clearing Electrode

- Ref: Collimator for test
 - Head: 90mm x 5 mm x 4 mm (Cu-coated Al_2O_3)
 - Support: 6mm x 4 mm x 30 mm (Al_2O_3 , Ti coating $\sim 1\mu\text{m}$)
 - Resistivity = 2.4 k Ω
 - $\delta t \sim 125$ @1.3 GHz (t : thickness of coating)
 - Beam test is now proceeding.

$$\delta = \sqrt{\frac{2}{\omega\mu\sigma}} : \text{Skin depth}$$



[Inside View]

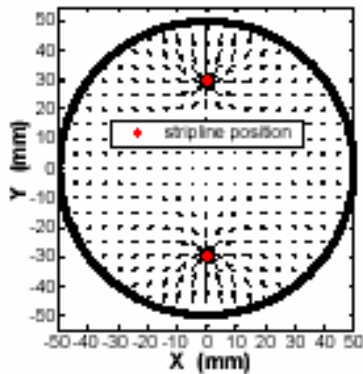


[Mask Head]



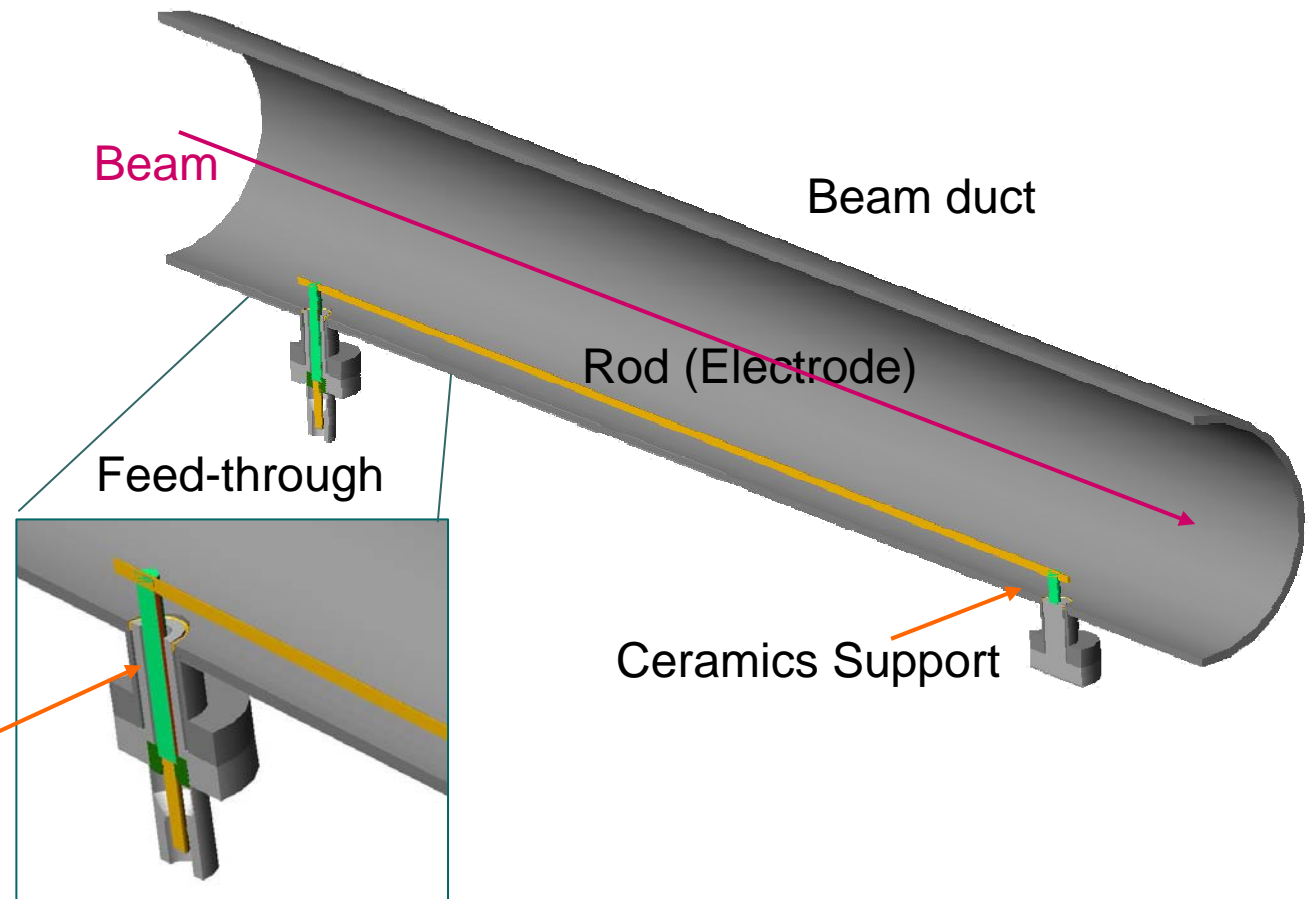
Clearing Electrode

- Concept of a clearing electrode
 - Model: Wire (Rod) type



L.Wang et al.,
EPAC2006

Ceramics Support
with thin metal
coating



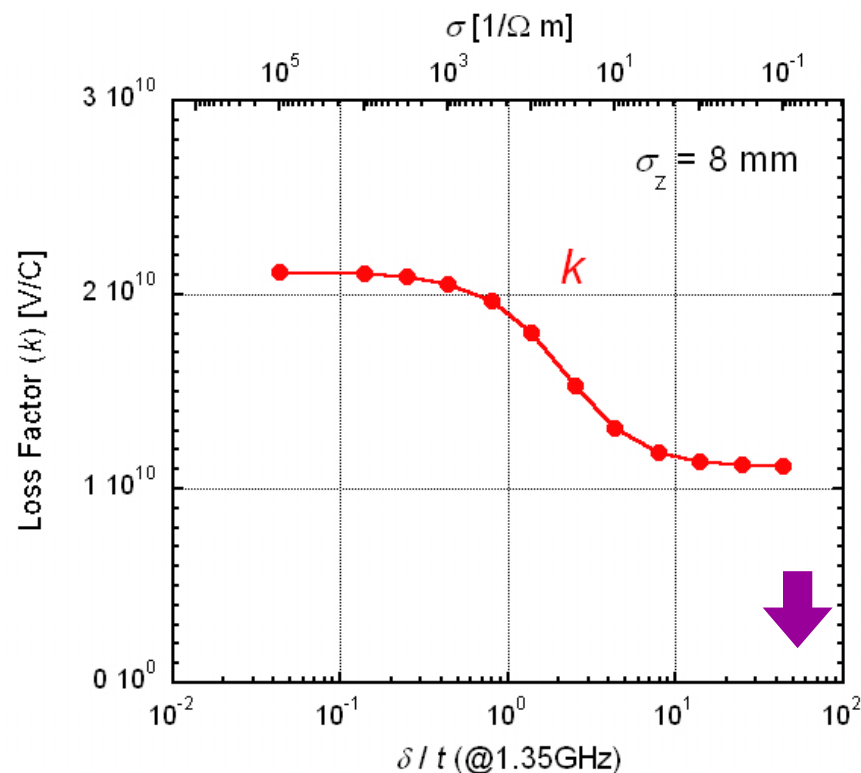
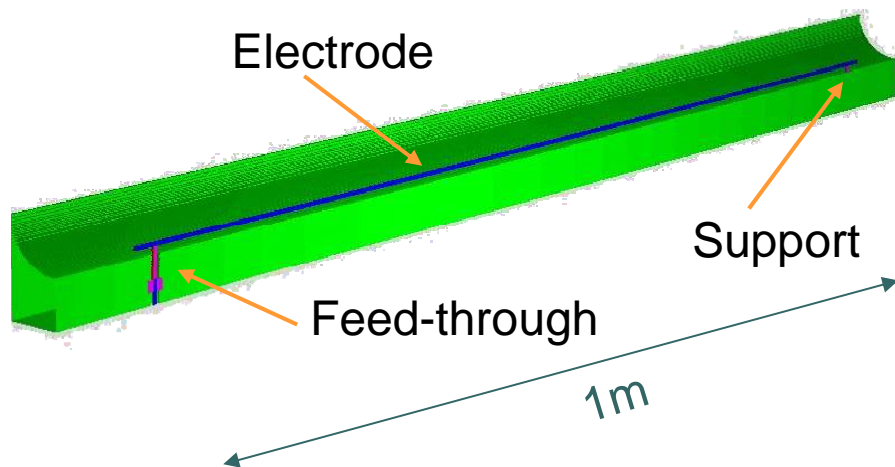
ECL2, CERN



Clearing Electrode

○ Calculated Loss factor by MAFIA

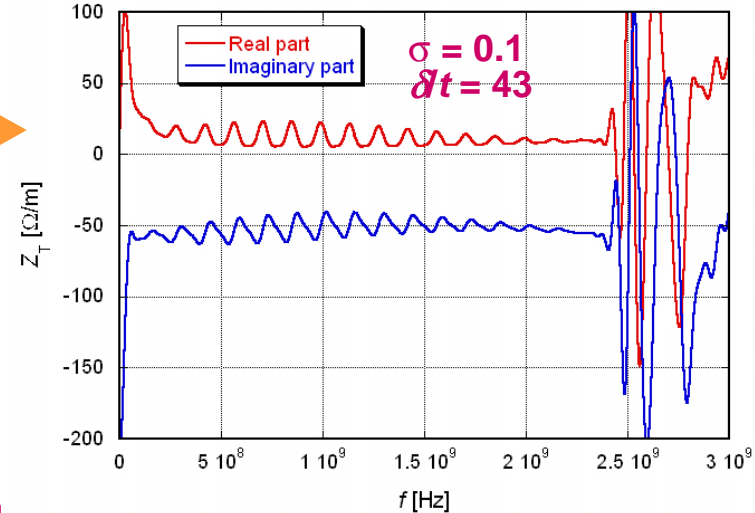
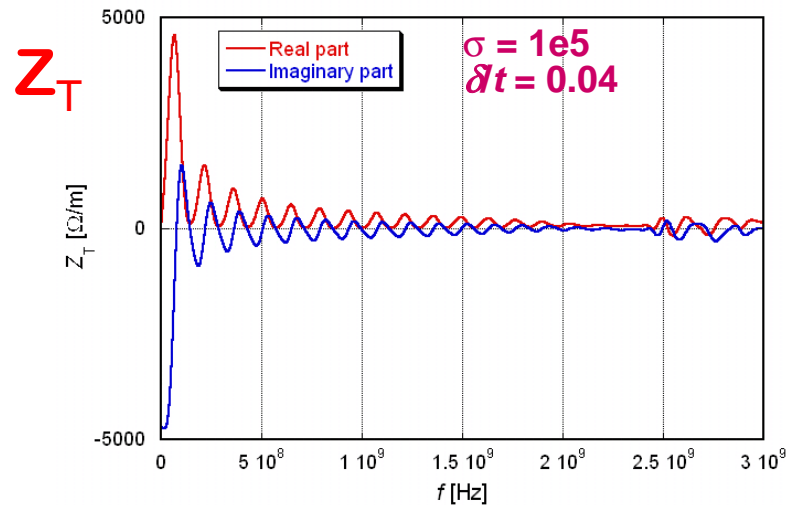
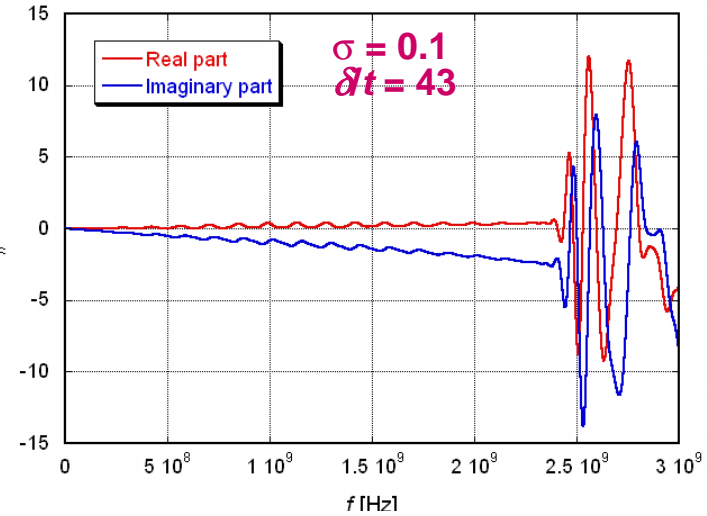
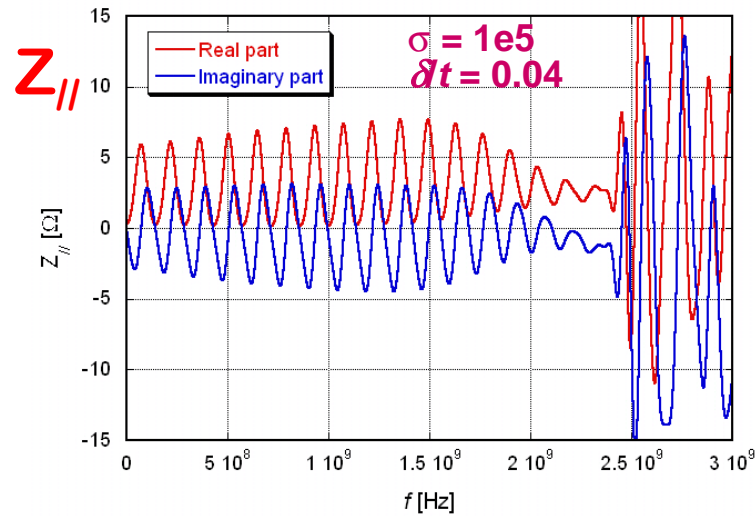
- Electrode (Rod): 8 mm from wall, $W3\text{mm}$, $H4\text{mm}$, $L1\text{m}$
- Support: $\phi 4.8\text{ mm}$ (Al_2O_3 , $\epsilon_r=9.0$)
- Metal coating: 0.8 mm thickness, $W2\text{mm}$, $L28\text{mm}$
- Duct: $\phi 94\text{mm}$, 2.4m
- Feed-through: $L40\text{mm}$
- 1/4 model (2 electrodes)
- Cal: 6m too short? → GdfidL?





Clearing Electrode

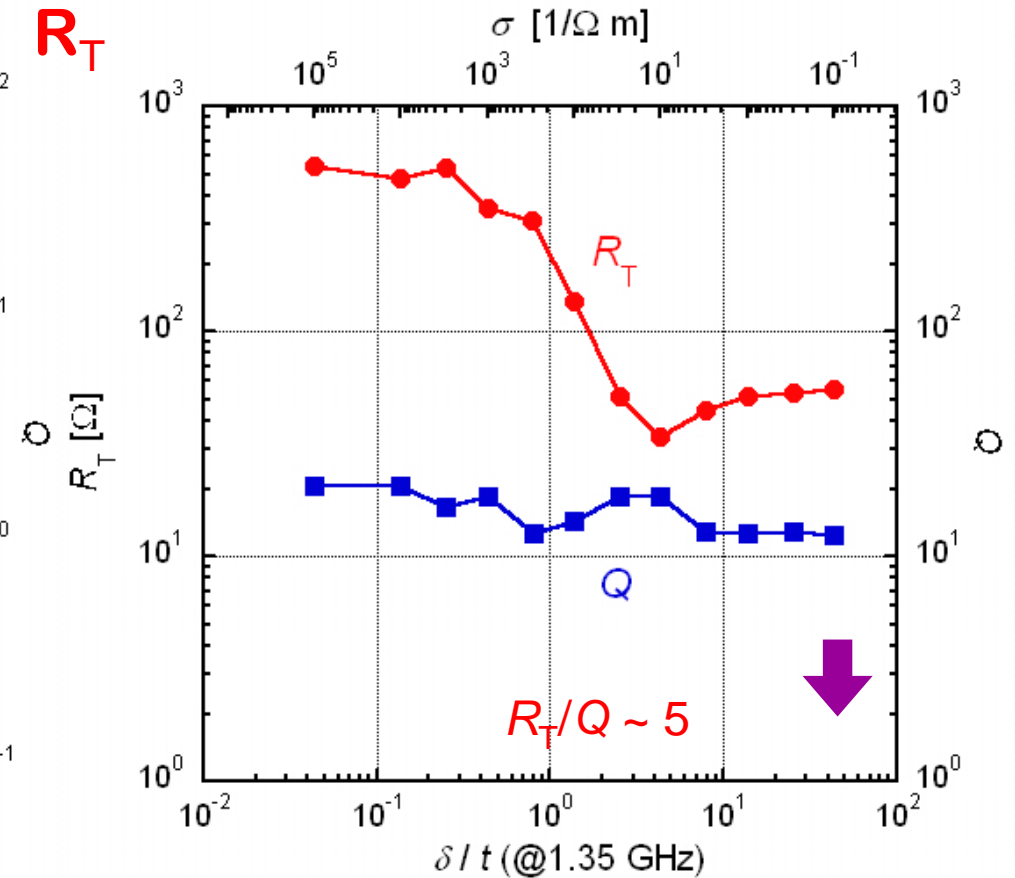
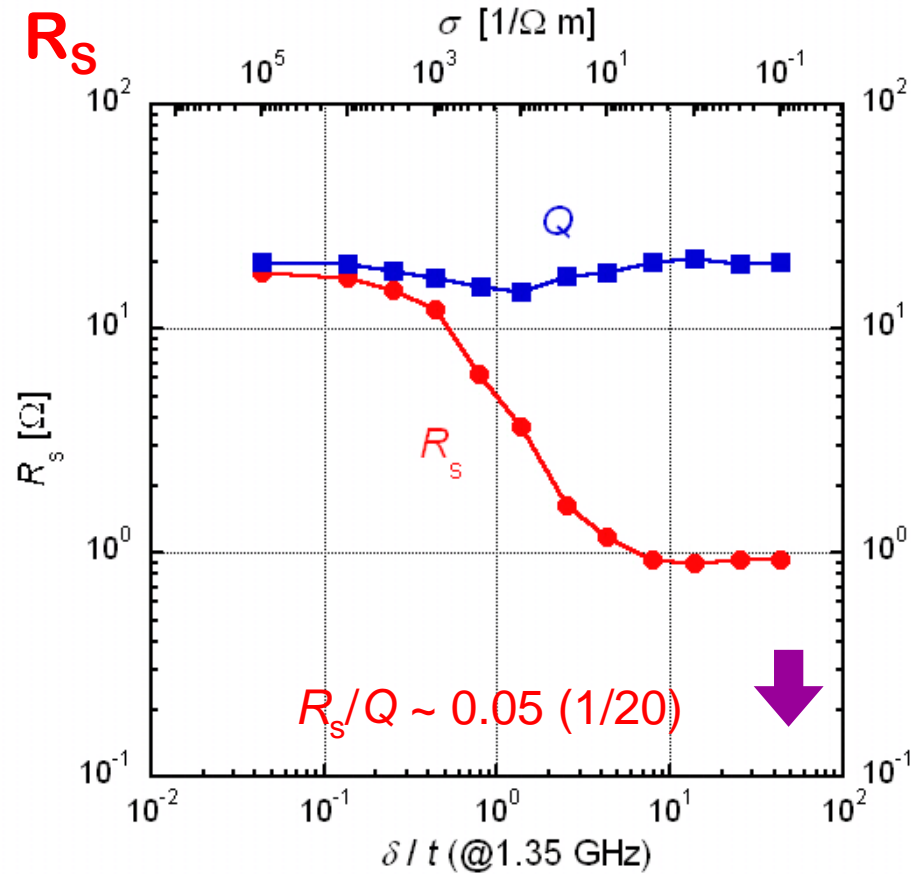
○ Calculated Impedance





Clearing Electrode

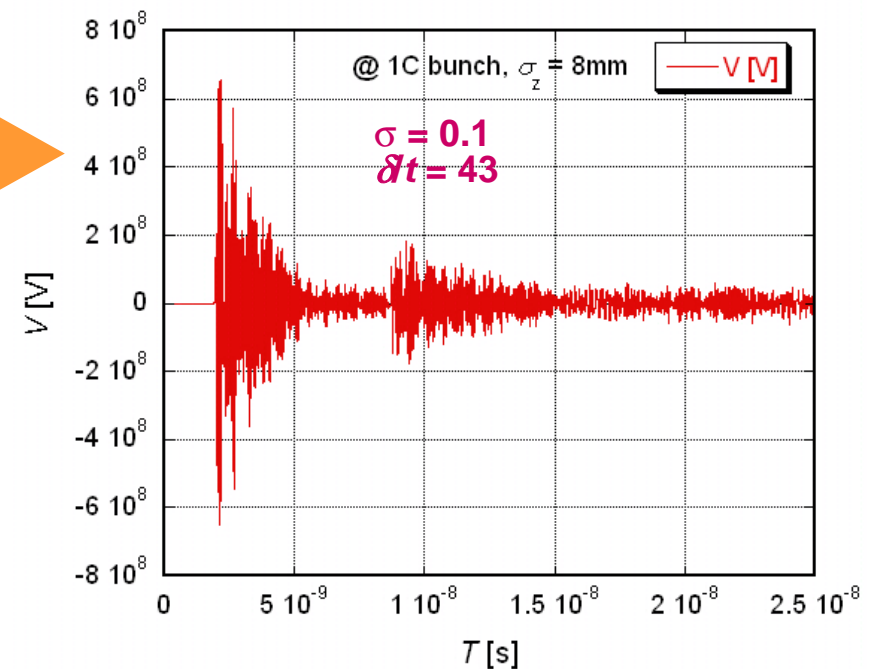
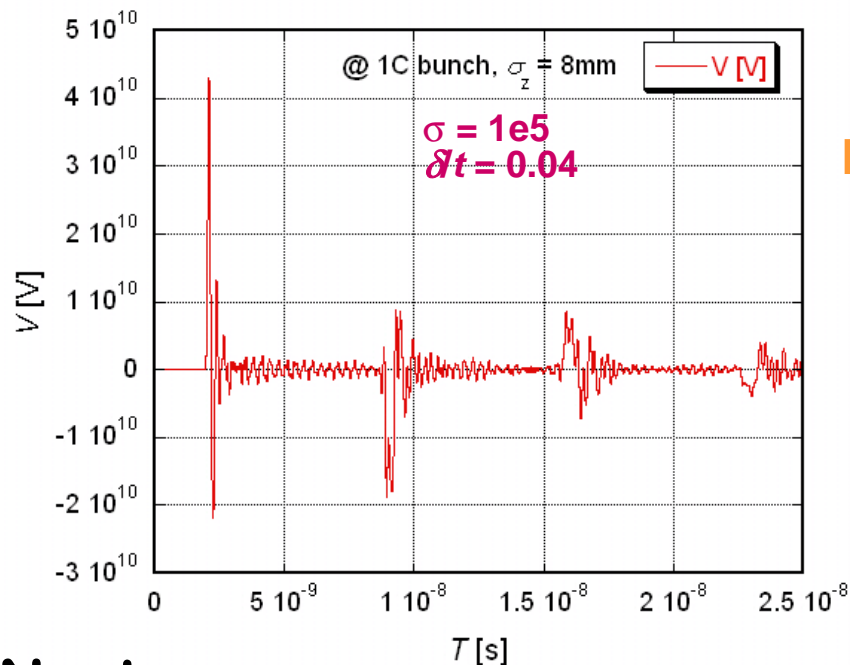
- Calculated shunt impedance at 1.35 GHz





Clearing Electrode

○ Output Voltage



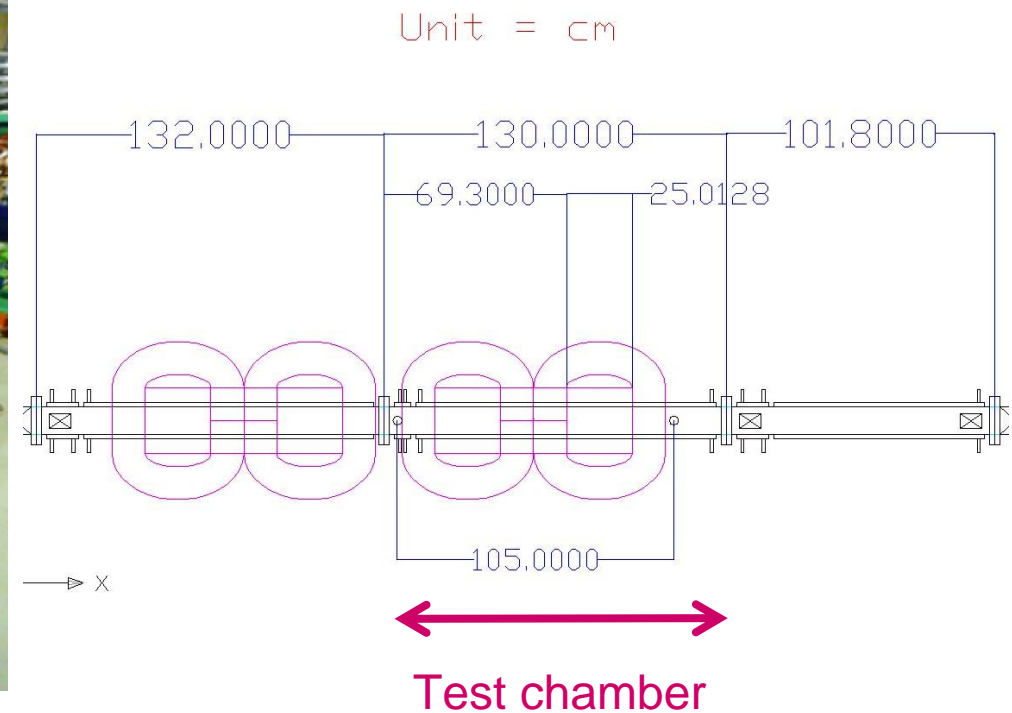
○ Next

- Reduce loss (thinner electrode??)
- Heating of electrode?
- Evaluation for CBI, Microwave Instability?
- Bending?, Other type??. etc.



Clearing Electrode

- Beam test at a wiggler section
 - Length of one magnet: 250 mm
 - $B_y = 0.75T$
 - Beam Duct: $\phi 94$ mm

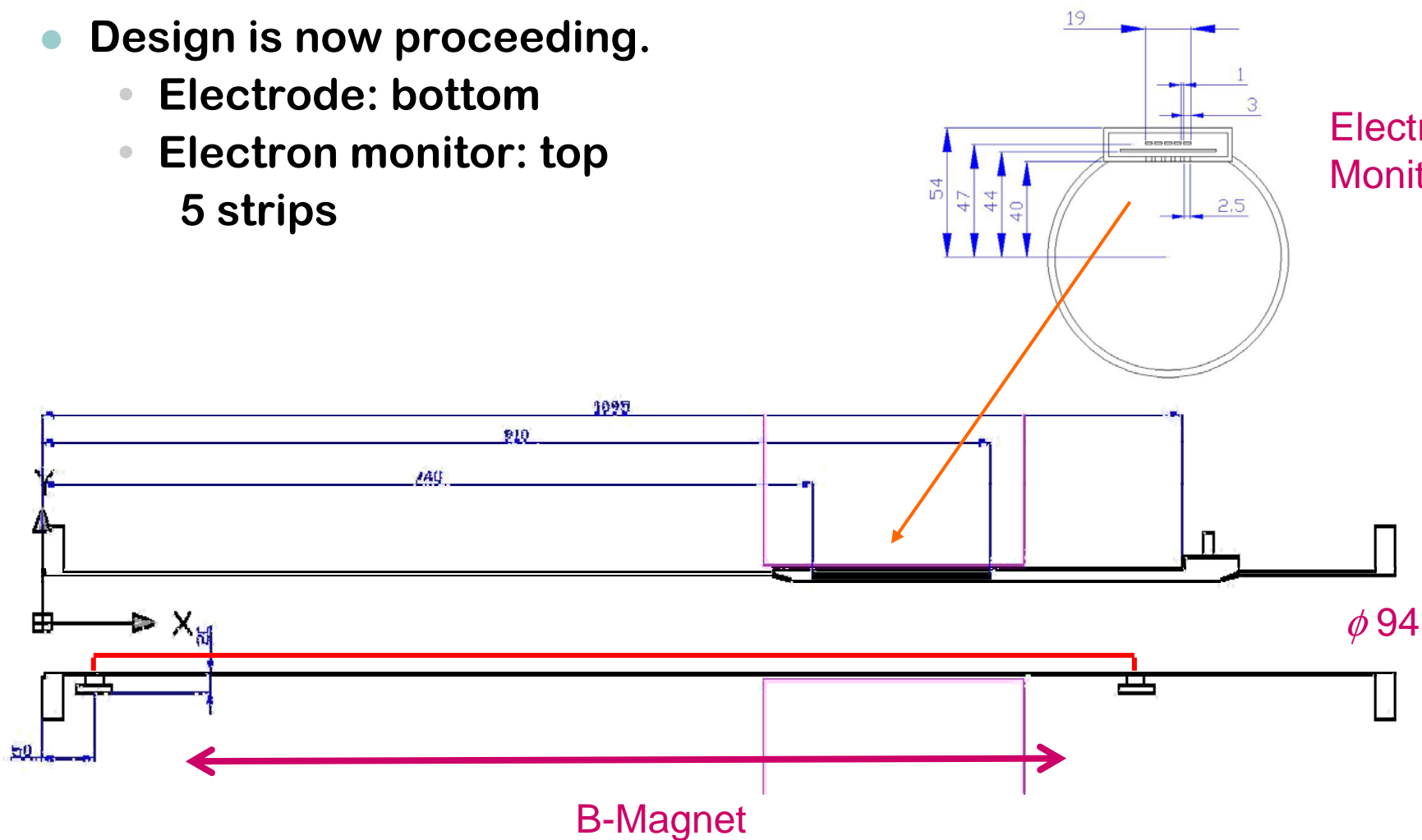




Clearing Electrode

○ Test Chamber

- Design is now proceeding.
 - Electrode: bottom
 - Electron monitor: top
5 strips





Summary



- R&D to suppress ECI effect has been proceeding at KEK using KEKB positron ring
- Beam duct with ante-chambers was found to be very effective to reduce photoelectrons, by several orders.
- TiN and NEG coatings reduce the electron density even at high current, by factors.
 - TiN coating seems the most promising one at present considering both PEY and SEY.
 - Experiments for a beam ducts with ante-chambers with TiN coating is planned.
- A rod type clearing electrode is now under consideration.
 - Calculation of RF properties are undergoing.
 - Beam test at a wiggler section is planned, where other types of clearing electrode, and surfaces, can be tested.



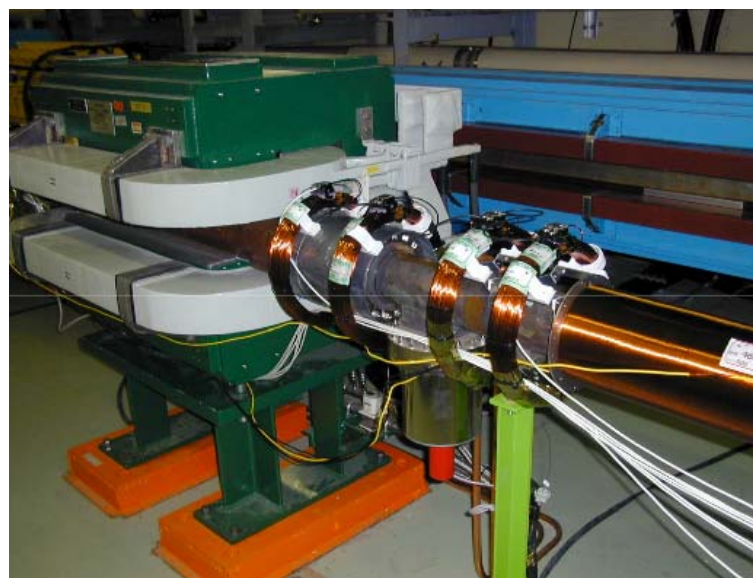
Beam Duct with Ante-chambers

- Solenoid field (2002~, mainly by H.Fukuma)
 - Suppression of vertical beam-size blow-up

Type	Length (mm)	Diameter (mm)	Turns	Bz (center) @ 5A (Gauss)
Bobbin	150 - 650	148	250(typ.)	45
Bobbinless	40	220	190, 200	48
Bobbinless	40	250	200	43
Bobbinless	40	300	200	37



2007/03/1-2



ECL2, CERN



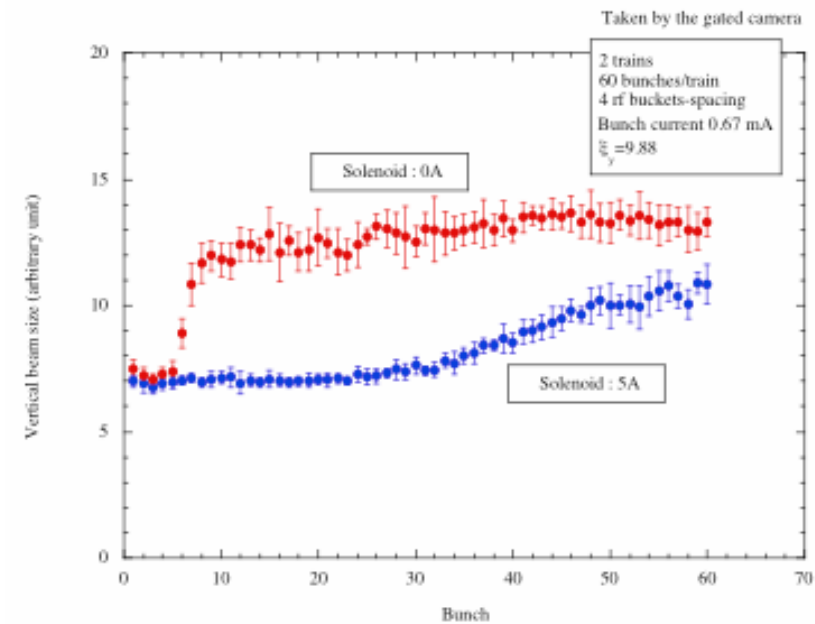
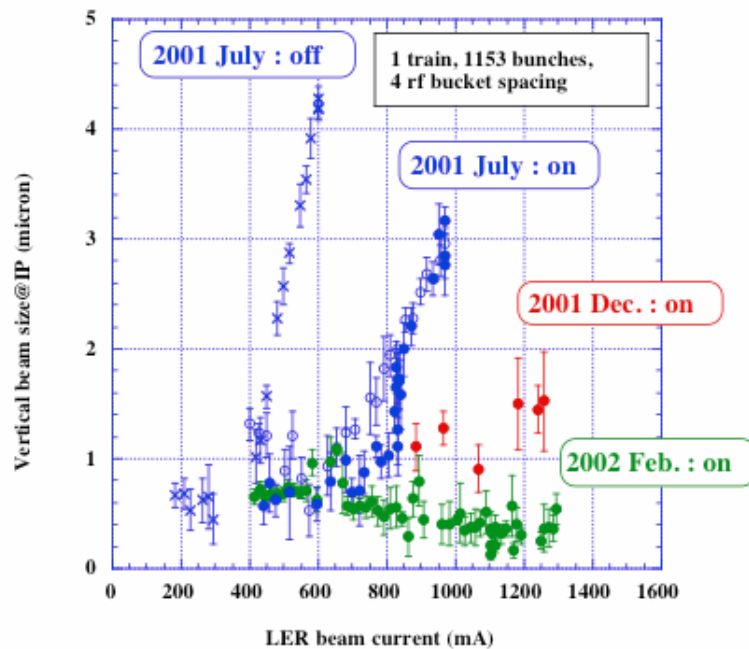
Beam Duct with Ante-chambers

○ Solenoid field (2002~, mainly by H.Fukuma)

● Suppression of vertical beam-size blow-up

Long train for physics run (4 rf buckets spacing)

Vertical beam size along train





Beam Duct with Ante-chambers

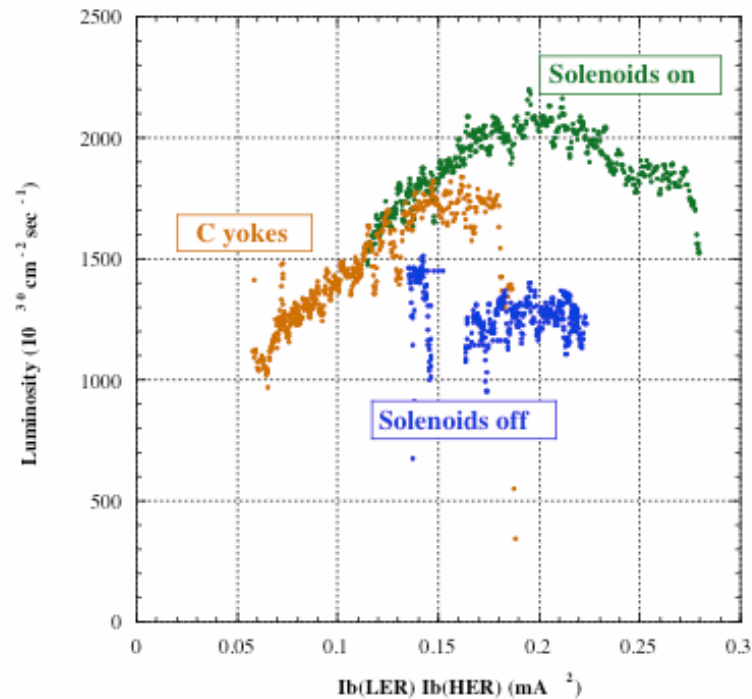
○ Solenoid field (2002~, mainly by H.Fukuma)

- **Suppression of vertical beam-size blow-up**

Luminosity

Specific luminosity

After 1st installation



Effect of solenoid (after second installation)

